



# Solidigm™ D3-S4520/D3-S4620

(Formerly Intel®)  
Product Specification

May 2024  
Revision 004

Solidigm Confidential

# SOLIDIGM™

## Solidigm™ D3-S4520/D3-S4620

- Capacities:
  - D3-S4520:
    - 2.5 inch - 240GB, 480GB, 960GB, 1.92TB, 3.84TB, 7.68TB
    - M.2 - 240GB, 480GB
  - D3-S4620:
    - 2.5 inch - 480GB, 960GB, 1.92TB, 3.84TB
- Components
  - Solidigm™ 3D NAND TLC Flash Memory
- Form Factor: 2.5 inch, M.2
- Random Read and Write IOPS<sup>1,2,3</sup>
  - 4KB<sup>4</sup> Random R/W QD32: Up to 92,000/60,000 IOPS
  - 8KB<sup>4</sup> Random R/W QD32: Up to 56,000/32,000 IOPS
- Sequential Read and Write Performance<sup>1,3</sup>
  - 128KB Seq. R/W QD32: Up to 550/510 MB/s<sup>5</sup>
- Endurance
  - D3-S4520: Up to 36.5 PBW<sup>6</sup> (JESD219 workload)
  - D3-S4620: Up to 35.1 PBW<sup>6</sup> (JESD219 workload)
- Latency
  - 4K Sequential Latency (Max) R/W: 37/40 µs
  - 4K Random Latency (Max) R/W: 104/63 µs
- Quality of Service<sup>7,8</sup>
  - Read/Write (Max): 150/3100 µs (99.9%)
- Read/Write Performance Consistency<sup>8,9</sup>
  - Up to 90%/80%
- Hardware-based AES-256 Encryption activated with ATA password
- Product Ecological Compliance
  - RoHS
- Certifications and Declarations
  - UL, CE, RMC Mark, BSMI, KCC, Microsoft WHCK, VCCI, SATA-IO
- Compliance
  - SATA Revision 3.2; compatible with SATA 6Gb/s, 3Gb/s and 1.5Gb/s interface rates
  - ATA/ATAPI Command Set - 3 (ACS-3 Rev 5); includes SCT (Smart Command Transport) and device statistics log support
  - Enhanced SMART ATA feature set
  - Native Command Queuing (NCQ) command set
  - Data set management Trim command
- Power
  - 2.5 inch: 5V or 5V+12V SATA Supply Rail<sup>10</sup>
  - M.2: 3.3V SATA Supply Rail
  - SATA Interface Power Management
  - OS-aware hot plug/removal (2.5 inch only)
  - Enhanced power-loss data protection feature
  - D3-S4520: Active/Idle: Up to 4.3 W/1.4 W (Typ.)<sup>8,11</sup>
  - D3-S4620: Active/Idle: Up to 3.9 W/1.3 W (Typ.)<sup>8,11</sup>
- Weight
  - 2.5": <70 grams
  - M.2: <40 grams
- Temperature
  - Operating: 0° C to 70° C (SMART) with specified airflow
  - Non-Operating<sup>12</sup>: -55° C to 95° C
  - Temperature monitoring and logging
  - Thermal throttling at 73° C (2.5 inch), 71° C (M.2) (SMART) when approaching max. operating temperature
- Shock (operating and non-operating)
  - 1000G (0.5ms)
- Vibration
  - Operating: 2.17 GRMS (5-700 Hz)
  - Non-Operating: 3.13 GRMS (5-800 Hz)
- Reliability
  - Uncorrectable Bit Error Rate (UBER): 1 sector per 10<sup>17</sup> bits read
  - Mean Time Between Failures (MTBF): 2 million hours
  - End-to-End data protection
  - Power Loss Protection
- Compatibility
  - WinPE
  - Windows Server 2012 R2, 2016, 2019
  - VMWare ESXi 6.5, 6.7
  - Red Hat Enterprise Linux 6.10, 7.6, 8.1
  - SUSE Linux Enterprise Server 11 SP4, 12 SP3, 15 SP1
  - CentOS 64bit 6.3, 7.7, 8.0

**Note:**

1. Performance values vary by capacity and form factor
2. Performance specifications apply to both compressible and incompressible data
3. See performance data in the Contents section for details.
4. 4 KB = 4,096 bytes; 8 KB = 8,192 bytes
5. MB/s = 1,000,000 bytes/second
6. 1PB =  $10^{15}$  Bytes
7. Based on Random 4KB QD=1 workload, measured at the time taken for 99.9<sup>th</sup> percentile of commands to finish the round-trip from host to drive and back to host
8. Measurement taken once the workload has reached steady state but including all background activities required for normal operation and data reliability
9. Based on Random 4KB QD=32 workload, measured as the ratio (IOPS in the 99.9<sup>th</sup> percentile slowest 1 second interval)/ (average IOPS during the test)
10. If both 12V and 5V power supplies are present, defaults to 5V + 12V power supplies. Does not support 12 volt only.
11. Based on 5V power supply
12. Contact your Solidigm representative for details on the non-operating temperature range

## Ordering Information

Contact your local Solidigm sales representative for ordering information.

## Revision History

Revision	Description	Date
001	<ul style="list-style-type: none"> <li>Initial Release</li> </ul>	June 2021
002	<ul style="list-style-type: none"> <li>Updated document template</li> <li>Updated notes for drive-to-drive performance variation</li> </ul>	July 2023
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004	<ul style="list-style-type: none"> <li>Updated Mechanical Information</li> </ul>	May 2024

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## Test and System Configuration

CPU: Intel® Xeon® Gold 6254 @ 3.10GHz 18 Cores, BIOS: SE5C620.86B.02.01.0009.092820190230, CPU Sockets: 2, RAM Capacity: 32G RAM Model: DDR4, RAM Stuffing: 1 of 4 channels, DIMM Slots Populated: Slot(s): 4, PCIe Attach: CPU (not PCH lane attach), Chipset: Intel® C624 Chipset, C-states: Disabled, Hyper Threading: Disabled, CPU Governor (through OS): Performance Mode (Default Mode: Balanced), OS: CentOS 7.5.1804, Kernel: 4.14.74

# Contents

1	Overview.....	4
1.1	Terms and Acronyms.....	4
2	Product Specifications.....	7
2.1	Capacity.....	7
2.2	Performance.....	7
2.3	Electrical Characteristics.....	16
2.4	Environmental Conditions.....	19
2.5	Thermal Throttling.....	20
2.5.1	Boundary Condition.....	23
2.6	Product Regulatory Compliance.....	26
2.7	Reliability Specifications.....	27
2.8	Temperature Sensor.....	29
2.9	Power Loss Capacitor Test.....	29
2.10	Hot Plug Support.....	30
2.11	Hardware Based AES-XTS 256-bit Encryption Activated with ATA Password.....	30
3	Mechanical Information.....	31
4	Pin and Signal Descriptions.....	33
4.1	2.5-inch Form Factor Pin Locations.....	33
4.2	M.2 Form Factor Pin Locations.....	33
4.3	Connector Pin Signal Definitions.....	34
4.4	Power Pin Signal Definitions.....	34
5	Supported Command Sets.....	38
5.1	ATA General Feature Command Set.....	38
5.2	Power Management Command Set.....	38
5.3	Sanitize Feature Set.....	39
5.4	Security Mode Feature Set.....	39
5.5	SMART Command Set.....	39
5.5.1	Attributes.....	39
5.5.2	Timed Workload Endurance Indicators.....	43
5.5.2.1	Timed Workload Media Wear Indicator – ID E2h.....	43
5.5.2.2	Timed Workload Host Reads Percentage – ID E3h.....	43
5.5.2.3	Workload Timer – ID E4h.....	43
5.5.2.4	User Notes.....	43
5.5.2.5	Example Use Cases.....	44
5.5.2.6	Use Case 1 - With a System Capable of SMART Commands.....	44
5.5.2.7	Use Case 2 - With a System Not Capable of SMART Commands.....	44
5.5.2.8	Example Calculation of Drive Wear.....	44
5.5.3	SMART Logs.....	45
5.6	Device Statistics.....	45
5.7	SMART Command Transport (SCT).....	47
5.8	Data Set Management Command Set.....	47

5.9 Accessible Max Address Configuration Command Set.....	47
5.10 48-Bit Address Command Set.....	47
5.11 General Purpose Log Command Set.....	48
5.12 Native Command Queuing.....	48
5.13 Software Settings Preservation.....	48
6 Certifications and Declarations.....	49
7 References.....	52
Appendix.....	53
Appendix A:IDENTIFY Device Command Data.....	53

## List of Figures

Figure 2.1: Thermal Throttling Behavior (2.5 inch).....	21
Figure 2.2: Thermal Throttling Behavior (M.2).....	22
Figure 2.3: Solidigm™ D3-S4520 Operating Domain Curves (2.5 inch).....	23
Figure 2.4: Solidigm™ D3-S4520 Operating Domain Curves (M.2).....	24
Figure 2.5: Solidigm™ D3-S4620 Operating Domain Curves (2.5 inch).....	25
Figure 2.6: Drive Test Setup for Wind Tunnel Characterization.....	26
Figure 3.1: Solidigm™ D3-S4520/D3-S4620 2.5 inch 7mm Dimensions.....	31
Figure 3.2: Solidigm™ D3-S4520 M.2 Dimensions.....	32
Figure 4.1: Layout of 2.5-inch Form Factor Signal and Power Segment Pins.....	33
Figure 4.2: Layout of M.2 Form Factor Signal and Power Segment Pins.....	34

## List of Tables

Table 1: Glossary of Terms and Acronyms.....	4
Table 2: User Addressable Sectors (LBA) - D3-S4520/D3-S4620.....	7
Table 3: Random Read/Write Input/Output Operations Per Second (IOPS) - D3-S4520.....	7
Table 4: Random Read/Write Input/Output Operations Per Second (IOPS) - D3-S4620.....	8
Table 5: Random Read/Write IOPS Consistency - D3-S4520.....	9
Table 6: Random Read/Write IOPS Consistency - D3-S4620.....	9
Table 7: Sequential Read and Write Bandwidth (MB/s) - D3-S4520.....	10
Table 8: Sequential Read and Write Bandwidth (MB/s) - D3-S4620.....	11
Table 9: Latency (TYP) - D3-S4520.....	11
Table 10: Latency (TYP) - D3-S4620.....	12
Table 11: Quality of Service (QoS) - D3-S4520.....	12
Table 12: Quality of Service (QoS) - D3-S4620.....	14
Table 13: Time to Ready (TTR)1 - D3-S4520.....	15
Table 14: Time to Ready (TTR)1 - D3-S4620.....	15
Table 15: Operating Voltage.....	16
Table 16: Power Consumption (5V Supply) - D3-S4520.....	17
Table 17: Power Consumption (5V Supply) - D3-S4620.....	17
Table 18: Power Consumption (5V + 12V Supply) - D3-S4520.....	18

Table 19:	Power Consumption (5V + 12V Supply) - D3-S4620.....	18
Table 20:	Power Consumption (3.3V Supply) - D3-S4520 (M.2).....	19
Table 21:	Temperature, Shock, Vibration, Altitude.....	19
Table 22:	Solidigm™ D3-S4520/D3-S4620 Thermal Throttle Settings.....	22
Table 23:	Product Regulatory Compliance Specifications.....	27
Table 24:	Reliability Specifications.....	28
Table 25:	Endurance Rating - D3-S4520.....	28
Table 26:	Endurance Rating - D3-S4620.....	29
Table 27:	Serial ATA Connector Pin Signal Definitions - 2.5-inch Form Factors.....	34
Table 28:	Serial ATA Power Pin Definitions—2.5-inch Form Factors.....	35
Table 29:	Serial ATA Power Pin Definitions-M.2 Form Factor Drives.....	36
Table 30:	SMART Attributes.....	40
Table 31:	SMART Attribute Status Flags.....	43
Table 32:	Device Statistics.....	45
Table 33:	Device Certifications and Declarations.....	49
Table 34:	Standards References.....	52
Table 35:	Returned Sector Data.....	53

# 1 Overview

This document describes the specifications and capabilities of the Solidigm™ D3-S4520/D3-S4620.

Solidigm™ D3-S4520/D3-S4620 delivers great performance and Quality of Service combined with high reliability for Serial Advanced Technology Attachment (SATA)-based computers in a 2.5-inch and M.2 form factor in capacities of 240GB, 480GB, 960GB, 1.92TB, 3.84TB and 7.68TB.

By combining Solidigm™ 3D NAND TLC Flash Memory technology with SATA 6 Gb/s interface support, D3-S4520/D3-S4620 delivers Sequential Read speeds of up to 550 MB/s and Sequential Write speeds of up to 510 MB/s. D3-S4520/D3-S4620 also delivers Random 4K Read speeds of up to 92,000 IOPS and Random 4K Write speeds of up to 60,000 IOPS, and Quality of Service of 0.25 ms for random 4KB reads measured at a queue depth of 1.

The industry-standard 2.5-inch and M.2 form factors enable interchangeability with existing hard disk drives (HDDs) and native SATA HDD drop-in replacement with the enhanced performance, reliability, ruggedness, and power savings offered by an SSD.

Solidigm™ D3-S4520/D3-S4620 offers these key features:

- Standard/Medium Endurance Technology
- High I/O and throughput performance
- Consistent I/O latency
- Tested and Proven power-loss data protection with self-test
- Proven End-to-End data protection, Demonstrated  $10^{17}$  UBER
- Thermal throttling
- Temperature Sensor
- Inrush current management
- Low power
- High reliability
- Temperature monitor and logging
- <5% Performance Degradation over product life

## 1.1 Terms and Acronyms

Table 1: Glossary of Terms and Acronyms

Term	Definition
ATA	Advanced Technology Attachment
CRC	Cyclic Redundancy Check
DAS	Device Activity Signal
DMA	Direct Memory Access
ECC	Error Correction Code
EEPROM	Electrically Erasable Programmable Read Only Memory
EXT	Extended



**Table 1: Glossary of Terms and Acronyms**

Term	Definition
FPDMA	First Party Direct Memory Access
GB	Gigabyte <b>Note:</b> The total usable capacity of the SSD may be less than the total physical capacity because a small portion of the capacity is used for NAND flash management and maintenance purposes.
Gb	Gigabit
HDD	Hard Disk Drive
HET	High Endurance Technology
I/O	Input/ Output
IOPS	Input/ Output Operations Per Second
ISO	International Standards Organization
KB	Kilobyte
LBA	Logical Block Address
MB	Megabyte (1,000,000 bytes)
TLC	Triple-level Cell
MTBF	Mean Time Between Failures
NCQ	Native Command Queuing
NOP	No Operation
PB	Petabyte
PCB	Printed Circuit Board
PIO	Programmed Input/Output
RDT	Reliability Demonstration Test
RMS	Root Mean Square
SATA	Serial Advanced Technology Attachment
SCT	SMART Command Transport
SMART	Self-Monitoring, Analysis and Reporting Technology. This is an open standard for developing hard drives and software systems that automatically monitors the health of a drive and reports potential problems.
SSD	Solid State Drive
TB	Terabyte
TBD	To Be Determined
TYP	Typical

Table 1: Glossary of Terms and Acronyms

Term	Definition
UBER	Uncorrectable Bit Error Rate

## 2 Product Specifications

### 2.1 Capacity

Table 2: User Addressable Sectors (LBA) - D3-S4520/D3-S4620

Capacity <sup>1</sup>	Unformatted Capacity (Total User Addressable Sectors in LBA Mode) <sup>2</sup>
	Solidigm™ D3-S4520/D3-S4620
240GB	468,862,128
480GB	937,703,088
960GB	1,875,385,008
1.92TB	3,750,748,848
3.84TB	7,501,476,528
7.68TB	15,002,931,888

**Note:**

- 1GB = 1,000,000,000 bytes; 1 sector = 512 bytes.
- LBA count shown represents total user storage capacity and will remain the same throughout the life of the drive. The total usable capacity of the SSD may be less than the total physical capacity because a small portion of the capacity is used for NAND flash management and maintenance purposes.

### 2.2 Performance

Table 3: Random Read/Write Input/Output Operations Per Second (IOPS) - D3-S4520

Form Factor	Capacity	Solidigm™ D3-S4520					
		Specification <sup>1,2,3,4</sup>					
		Random 4KB Read	Random 4KB Write	Random 8KB Read	Random 8KB Write	Random 4KB 70/30 Read/Write	Random 8KB 70/30 Read/Write
2.5" 7mm	240GB	44,000	15,500	22,000	8,000	27,000	13,500
	480GB	79,000	30,000	40,000	15,000	43,000	23,000
	960GB	90,000	43,000	56,000	22,000	56,000	31,000
	1.92TB	91,000	38,000	56,000	22,000	57,000	33,000
	3.84TB	92,000	31,000	56,000	22,000	56,000	32,000

**Table 3: Random Read/Write Input/Output Operations Per Second (IOPS) - D3-S4520**

Form Factor	Capacity	Solidigm™ D3-S4520					
		Specification <sup>1,2,3,4</sup>					
		Random 4KB Read	Random 4KB Write	Random 8KB Read	Random 8KB Write	Random 4KB 70/30 Read/Write	Random 8KB 70/30 Read/Write
	7.68TB	86,000	30,000	56,000	15,500	57,000	33,000
M.2	240GB	42,000	14,500	20,000	7,000	25,000	12,500
	480GB	85,000	48,000	45,000	24,000	56,000	29,500

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 5% variation in performance between drive to drive runs. Any change in the system or drive configuration may impact drive performance.
4. 4KB = 4,096 bytes; 8KB = 8,192 bytes.

**Table 4: Random Read/Write Input/Output Operations Per Second (IOPS) - D3-S4620**

Form Factor	Capacity	Solidigm™ D3-S4620					
		Specification <sup>1,2,3,4</sup>					
		Random 4KB Read	Random 4KB Write	Random 8KB Read	Random 8KB Write	Random 4KB 70/30 Read/Write	Random 8KB 70/30 Read/Write
2.5" 7mm	480GB	85,000	48,000	45,000	25,000	57,000	31,500
	960GB	90,000	54,000	56,000	30,000	62,000	36,000
	1.92TB	91,000	53,000	56,000	32,000	67,000	41,000
	3.84TB	91,000	60,000	56,000	32,000	70,000	44,000

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 5% variation in performance between drive to drive runs. Any change in the system or drive

configuration may impact drive performance.

4. 4KB = 4,096 bytes; 8KB = 8,192 bytes.

**Table 5: Random Read/Write IOPS Consistency - D3-S4520**

Form Factor	Capacity	Solidigm™ D3-S4520			
		Specification <sup>1,2,3,4</sup>			
		Random 4KB Read	Random 4KB Write	Random 8KB Read	Random 8KB Write
2.5" 7mm	240GB	90%	40%	90%	40%
	480GB	90%	70%	90%	70%
	960GB	90%	80%	90%	80%
	1.92TB	90%	80%	90%	80%
	3.84TB	90%	80%	90%	80%
	7.68TB	90%	80%	90%	80%
M.2	240GB	90%	30%	90%	30%
	480GB	90%	77%	90%	77%

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 10% variation in consistency between drive to drive runs. Any change in the system or drive configuration may impact drive performance.
4. 4KB = 4,096 bytes; 8KB = 8,192 bytes.

**Table 6: Random Read/Write IOPS Consistency - D3-S4620**

Form Factor	Capacity	Solidigm™ D3-S4620			
		Specification <sup>1,2,3,4</sup>			
		Random 4KB Read	Random 4KB Write	Random 8KB Read	Random 8KB Write
2.5" 7mm	480GB	90%	77%	90%	77%
	960GB	90%	80%	90%	80%
	1.92TB	90%	80%	90%	80%
	3.84TB	90%	80%	90%	80%

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 10% variation in consistency between drive to drive runs. Any change in the system or drive configuration may impact drive performance.
4. 4KB = 4,096 bytes; 8KB = 8,192 bytes

**Table 7: Sequential Read and Write Bandwidth (MB/s) - D3-S4520**

Form Factor	Capacity	Solidigm™ D3-S4520	
		Specification <sup>1,2,3,4</sup>	
		128KB Sequential Read QD32	128KB Sequential Write QD32
2.5" 7mm	240GB	470	233
	480GB	550	460
	960GB	550	510
	1.92TB	550	510
	3.84TB	550	510
	7.68TB	550	510
M.2	240GB	400	233
	480GB	550	500

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 5% variation in consistency between drive to drive runs. Any change in the system or drive configuration may impact drive performance.
4. 128KB = 131,072 bytes.

Table 8: Sequential Read and Write Bandwidth (MB/s) - D3-S4620

Form Factor	Capacity	Solidigm™ D3-S4620	
		Specification <sup>1,2,3,4</sup>	
		128KB Sequential Read QD32	128KB Sequential Write QD32
2.5" 7mm	480GB	550	500
	960GB	550	510
	1.92TB	550	510
	3.84TB	550	510

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74 with Queue Depth 32. Measurements are performed on a full Logical Block Address (LBA) span of the drive. Performance with different Queue Depths will be provided upon request. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. Solidigm expects up to 5% variation in consistency between drive to drive runs. Any change in the system or drive configuration may impact drive performance.
4. 128KB = 131,072 bytes.

Table 9: Latency (TYP) - D3-S4520

Form Factor	Capacity	Solidigm™ D3-S4520			
		Specification <sup>1,2,3,4</sup>			
		Read Sequential (μs)	Read Random (μs)	Write Sequential (μs)	Write Random (μs)
2.5" 7mm	240GB	36	102	37	61
	480GB	36	102	36	48
	960GB	36	102	36	49
	1.92TB	37	104	38	54
	3.84TB	37	104	40	57
	7.68TB	37	103	37	57
M.2	240GB	36	102	36	63
	480GB	36	102	36	43

**Note:**

1. Latency measured using 4KB (4,096 bytes) transfer size with Queue Depth equal to 1 on a sequential and random workload.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
4. Measured as the time taken for 50.0 percentile of commands to finish the round-trip from host to drive and back to host. Performance collected with two hosts connected with only single host accessing the full span of the drive (single namespace).

**Table 10: Latency (TYP) - D3-S4620**

Form Factor	Capacity	Solidigm™ D3-S4620			
		Specification <sup>1,2,3,4</sup>			
		Read Sequential (μs)	Read Random (μs)	Write Sequential (μs)	Write Random (μs)
2.5" 7mm	480GB	36	103	36	43
	960GB	37	103	37	45
	1.92TB	37	104	38	47
	3.84TB	36	104	38	45

**Note:**

1. Latency measured using 4KB (4,096 bytes) transfer size with Queue Depth equal to 1 on a sequential and random workload.
2. Performance measured with drives sequentially pre-filled before measuring data.
3. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
4. Measured as the time taken for 50.0 percentile of commands to finish the round-trip from host to drive and back to host. Performance collected with two hosts connected with only single host accessing the full span of the drive (single namespace).

**Table 11: Quality of Service (QoS) - D3-S4520**

Form Factor	Capacity	Solidigm™ D3-S4520			
		Specification			
		Reads Queue Depth 1 (μs)	Reads Queue Depth 32 (μs)	Writes Queue Depth 1 (μs)	Writes Queue Depth 32 (μs)
Quality of Service <sup>1,2,3</sup> (99.9%)					



Table 11: Quality of Service (QoS) - D3-S4520

Form Factor	Capacity	Solidigm™ D3-S4520			
		Specification			
		Reads Queue Depth 1 (μs)	Reads Queue Depth 32 (μs)	Writes Queue Depth 1 (μs)	Writes Queue Depth 32 (μs)
2.5" 7mm	240GB	150	2200	2500	7700
	480GB	150	1500	500	5400
	960GB	150	900	600	3900
	1.92TB	150	800	900	2700
	3.84TB	150	800	1000	3700
	7.68TB	150	800	1300	3700
M.2	240GB	150	2300	3100	8500
	480GB	150	1400	300	2900
<b>Quality of Service <sup>1,2,3</sup> (99.9999%)</b>					
2.5" 7mm	240GB	1300	3900	8000	15000
	480GB	800	3100	2300	12000
	960GB	1200	2400	2300	8000
	1.92TB	1500	2400	2300	6500
	3.84TB	1000	2200	2400	7500
	7.68TB	800	2100	2400	7800
M.2	240GB	1800	4000	9000	16500
	480GB	1700	3100	2300	7000

**Note:**

- Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74. Quality of Service measured using 4KB (4,096 bytes) transfer size on a random workload on a full Logical Block Address (LBA) span of the drive once the workload has reached steady state but including all background activities required for normal operation and data reliability. Runtime is 3 hours. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
- Based on Random 4KB QD=1, 32 workloads, measured as the time taken for 99.9 (or 99.9999) percentile of commands to finish the round-trip from host to drive and back to host.
- Performance measured with drives sequentially pre-filled before measuring data.

Table 12: Quality of Service (QoS) - D3-S4620

Form Factor	Capacity	Solidigm™ D3-S4620			
		Specification			
		Reads Queue Depth 1 (μs)	Reads Queue Depth 32 (μs)	Writes Queue Depth 1 (μs)	Writes Queue Depth 32 (μs)
Quality of Service <sup>1,2,3</sup> (99.9%)					
2.5" 7mm	480GB	150	1400	300	3200
	960GB	150	900	400	1700
	1.92TB	150	800	450	1800
	3.84TB	150	800	400	2100
Quality of Service <sup>1,2,3</sup> (99.9999%)					
2.5" 7mm	480GB	900	3000	2300	7000
	960GB	700	2500	2300	5500
	1.92TB	1100	2300	2300	5600
	3.84TB	1100	2200	2100	6000

**Note:**

1. Performance measured using FIO version 3.5 on Linux OS: CentOS 7.5.1804 Kernel: 4.14.74. Quality of Service measured using 4KB (4,096 bytes) transfer size on a random workload on a full Logical Block Address (LBA) span of the drive once the workload has reached steady state but including all background activities required for normal operation and data reliability. Runtime is 3 hours. See Test and System Configuration [on page 4](#) for performance testing and configuration details.
2. Based on Random 4KB QD=1, 32 workloads, measured as the time taken for 99.9 (or 99.9999) percentile of commands to finish the round-trip from host to drive and back to host.
3. Performance measured with drives sequentially pre-filled before measuring data.

Table 13: Time to Ready (TTR)<sup>1</sup> - D3-S4520

Form Factor	Capacity	Solidigm™ D3-S4520		
		Specification		
		TTR after Planned Shutdown <sup>2</sup> Typical (seconds)	TTR after Unplanned Shutdown <sup>3</sup> Typical (seconds)	Standby Immediate Completion Typical (seconds)
2.5" 7mm	240GB	6	9	3
	480GB	8	9	3
	960GB	8	9	3
	1.92TB	8	9	3
	3.84TB	10	11	6
	7.68TB	20	25	12
M.2	240GB	6	9	3
	480GB	8	9	3

**Note:**

1. Time to Ready is measured from the time when the drive powers on to the time when the drive is ready to accept the first command from the host.
2. Planned Shutdown is preceded by STANDBY IMMEDIATE command. For 5% of the time, Time to Ready after Planned Shutdown is up to 12 seconds (240 GB - 3.84 TB) and 30 seconds (7.68TB).
3. For 5% of the time, Time to Ready after Unplanned Shutdown is up to 20 seconds (240 GB - 3.84 TB) and 30 seconds (7.68 TB).

Table 14: Time to Ready (TTR)<sup>1</sup> - D3-S4620

Form Factor	Capacity	Solidigm™ D3-S4620		
		Specification		
		TTR after Planned Shutdown <sup>2</sup> Typical (seconds)	TTR after Unplanned Shutdown <sup>3</sup> Typical (seconds)	Standby Immediate Completion Typical (seconds)
2.5" 7mm	480GB	8	9	3
	960GB	8	9	3
	1.92TB	8	9	3
	3.84TB	10	11	6

**Note:**

1. Time to Ready is measured from the time when the drive powers on to the time when the drive is ready to accept the first command from the host.
2. Planned Shutdown is preceded by STANDBY IMMEDIATE command. For 5% of the time, Time to Ready after Planned Shutdown is up to 12 seconds.
3. For 5% of the time, Time To Ready after Unplanned Shutdown is up to 20 seconds.

## 2.3 Electrical Characteristics

Table 15: Operating Voltage

Electrical Characteristics	Solidigm™ D3-S4520/D3-S4620
<b>5V Operating Characteristics:</b> Operating Voltage range Rise time (Max/Min) Fall time (Min) <sup>1</sup> Noise level Min Off time <sup>2</sup> Inrush Current (Typical Peak) <sup>3</sup>	5 V (±5%) 1 s / 1 ms 5 kV/s 500 mV pp 10 Hz - 100 KHz, 50 mV pp 100 KHz - 20 MHz 500 ms 1.5 A, < 1 s
<b>12V Operating Characteristics:</b> Operating Voltage range Rise time (Max/Min) Fall time (Min) <sup>1</sup> Noise level Min Off time <sup>2</sup> Inrush Current (Typical Peak) <sup>3</sup>	12 V (±10%) 1 s / 1 ms 12 kV/s 1000 mV pp 10 Hz - 100 KHz, 100 mV pp 100 KHz - 20 MHz 500 ms 1.5 A, < 1 s
<b>3.3V (M.2) Operating Characteristics:</b> Operating Voltage range Rise time (Max/Min) Fall time (Min) <sup>1</sup> Noise level Min Off time <sup>2</sup> Inrush Current (Typical Peak) <sup>3</sup>	3.3 V (±5%) 100 ms / 1 ms 3.3 kV/s 100 mV pp 10 Hz - 20 MHz 500 ms 1.5 A, < 1 s

**Note:**

1. Fall time must be equal or better than minimum to guarantee full functionality of enhanced power loss management.
2. The drive must be powered off for at least 500msec before powering on.
3. Measured from initial device power supply application.

**Table 16: Power Consumption (5V Supply) - D3-S4520**

Capacity	Solidigm™ D3-S4520				
	RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
	Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
240GB	2.3	1.9	2.5	2.4	1.0
480GB	3.0	2.0	3.3	2.6	1.2
960GB	3.1	2.1	4.5	2.7	1.1
1.92TB	3.1	2.1	6.0	2.8	1.1
3.84TB	3.7	2.2	7.6	3.1	1.2
7.68TB	4.3	2.5	9.1	3.4	1.4

**Note:**

1. The workload equates QD32/128KB Sequential Writes. Average power is measured over a 100ms sample period.
2. The workload equates QD32/128KB Sequential Reads. Average power is measured over a 100ms sample period.
3. The workload equates QD32/128KB Sequential Writes. Max. Burst power is measured over a 500  $\mu$ s sample period.
4. The workload equates QD32/128KB Sequential Reads. Max. Burst power is measured over a 500  $\mu$ s sample period.

**Table 17: Power Consumption (5V Supply) - D3-S4620**

Capacity	Solidigm™ D3-S4620				
	RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
	Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
480GB	2.9	2.0	3.5	2.5	1.0
960GB	3.2	2.0	4.6	2.6	1.3
1.92TB	3.3	2.2	6.4	2.9	1.2
3.84TB	3.9	2.2	7.9	3.0	1.3

**Note:**

1. The workload equates QD32/128KB Sequential Writes. Average power is measured over a 100ms sample period.
2. The workload equates QD32/128KB Sequential Reads. Average power is measured over a 100ms sample period.
3. The workload equates QD32/128KB Sequential Writes. Max. Burst power is measured over a 500  $\mu$ s sample period.
4. The workload equates QD32/128KB Sequential Reads. Max. Burst power is measured over a 500  $\mu$ s sample period.

**Table 18: Power Consumption (5V + 12V Supply) - D3-S4520**

Capacity	V	Solidigm™ D3-S4520				
		RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
		Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
240GB	5V	1.6	1.7	2.0	2.0	1.0
	12V	0.5	0.2	0.8	0.8	0.01
480GB	5V	1.9	1.8	2.5	2.2	1.0
	12V	1.0	0.2	1.4	0.7	0.01
960GB	5V	2.0	1.9	2.6	2.3	1.0
	12V	1.0	0.2	2.5	0.7	0.01
1.92TB	5V	2.0	1.7	2.6	2.4	1.1
	12V	1.0	0.2	4.0	3.6	0.01
3.84TB	5V	2.1	1.8	2.9	2.5	1.1
	12V	1.0	0.3	4.6	4.4	0.01
7.68TB	5V	2.4	2.2	3.2	2.6	1.3
	12V	1.2	0.2	5.0	0.8	0.01

**Note:**

1. The workload equates QD32/128KB Sequential Writes. Average power is measured over a 100ms sample period.
2. The workload equates QD32/128KB Sequential Reads. Average power is measured over a 100ms sample period.
3. The workload equates QD32/128KB Sequential Writes. Max. Burst power is measured over a 500  $\mu$ s sample period.
4. The workload equates QD32/128KB Sequential Reads. Max. Burst power is measured over a 500  $\mu$ s sample period.

**Table 19: Power Consumption (5V + 12V Supply) - D3-S4620**

Capacity	V	Solidigm™ D3-S4620				
		RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
		Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
480GB	5V	1.9	1.8	2.3	2.1	1.0
	12V	1.1	0.2	1.9	1.0	0.01
960GB	5V	2.0	1.9	2.5	2.2	1.1
	12V	1.0	0.2	2.6	0.8	0.01

**Table 19: Power Consumption (5V + 12V Supply) - D3-S4620**

Capacity	V	Solidigm™ D3-S4620				
		RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
		Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
1.92TB	5V	2.1	2.0	2.8	2.3	1.1
	12V	1.0	0.2	4.4	0.7	0.01
3.84TB	5V	2.1	1.8	2.7	2.6	1.1
	12V	1.1	0.2	5.3	4.3	0.01

**Note:**

1. The workload equates QD32/128KB Sequential Writes. Average power is measured over a 100ms sample period.
2. The workload equates QD32/128KB Sequential Reads. Average power is measured over a 100ms sample period.
3. The workload equates QD32/128KB Sequential Writes. Max. Burst power is measured over a 500  $\mu$ s sample period.
4. The workload equates QD32/128KB Sequential Reads. Max. Burst power is measured over a 500  $\mu$ s sample period.

**Table 20: Power Consumption (3.3V Supply) - D3-S4520 (M.2)**

Capacity	Solidigm™ D3-S4520 (M.2)				
	RMS Average Active Power (W)		Max. Burst Active Power (W)		Idle (W)
	Write <sup>1</sup>	Read <sup>2</sup>	Write <sup>3</sup>	Read <sup>4</sup>	
240GB	2.1	1.8	2.4	2.3	0.9
480GB	3.0	1.9	3.5	2.6	0.9

**Note:**

1. The workload equates QD32/128KB Sequential Writes. Average power is measured over a 100ms sample period.
2. The workload equates QD32/128KB Sequential Reads. Average power is measured over a 100ms sample period.
3. The workload equates QD32/128KB Sequential Writes. Max. Burst power is measured over a 500  $\mu$ s sample period.
4. The workload equates QD32/128KB Sequential Reads. Max. Burst power is measured over a 500  $\mu$ s sample period.

## 2.4 Environmental Conditions

**Table 21: Temperature, Shock, Vibration, Altitude**

Temperature		Range
Case Temperature	Operating <sup>1</sup> Non-operating <sup>2</sup>	0°C to 70°C -55°C to 95°C

**Table 21: Temperature, Shock, Vibration, Altitude**

Temperature		Range
Temperature Gradient <sup>3</sup>	Operating Non-operating	20°C/hr (Typical) 30°C/hr (Typical)
Humidity	Operating Non-operating	5 - 90 % 5 - 95 %

Shock and Vibration		Range
Shock <sup>4</sup>	Operating Non-operating	1000G (0.5ms) 1000G (0.5ms)
Vibration <sup>5</sup>	Operating Non-operating	2.17 GRMS (5-700 Hz) 3.13 GRMS (5-800 Hz)

Altitude		Range
Altitude	Operating Non-operating	-1,000 to 10,000 ft. -1,000 to 40,000 ft.

**Note:**

1. Operating temperature implies ambient air temperature under defined airflow. Operation temperature refers to Composition temperature.
2. Please contact your Solidigm representative for details on the non-operating temperature range.
3. Temperature gradient measured without condensation.
4. Shock specifications assume the SSD is mounted securely with the input vibration applied to the drive-mounting screws. Stimulus may be applied in the X, Y or Z axis. Shock specification is measured using Root Mean Squared (RMS) value.
5. Vibration specifications assume the SSD is mounted securely with the input vibration applied to the drive-mounting screws. Stimulus may be applied in the X, Y or Z axis. Vibration specification is measured using RMS value.

## 2.5 Thermal Throttling

Solidigm™ D3-S4520/D3-S4620 will provide performance throttling during high temperature scenarios to mitigate thermal challenges. Thermal throttling works by moving the power ceiling in N number of linear steps as shown in below.

Key definitions for important parameters are:

- $T_{start}$  - throttling starts
- $T_{max}$  - max throttling is applied
- $P_{maxdrop}$  - maximum drop allowed determined by the internal setting
- $T_{hysteresis}$  - 2C comes into play during the cooling phase to prevent rapid oscillations between the throttle states. The temperature must hit the hysteresis level to return the power ceiling back to previous levels.



Figure 2.1: Thermal Throttling Behavior (2.5 inch)

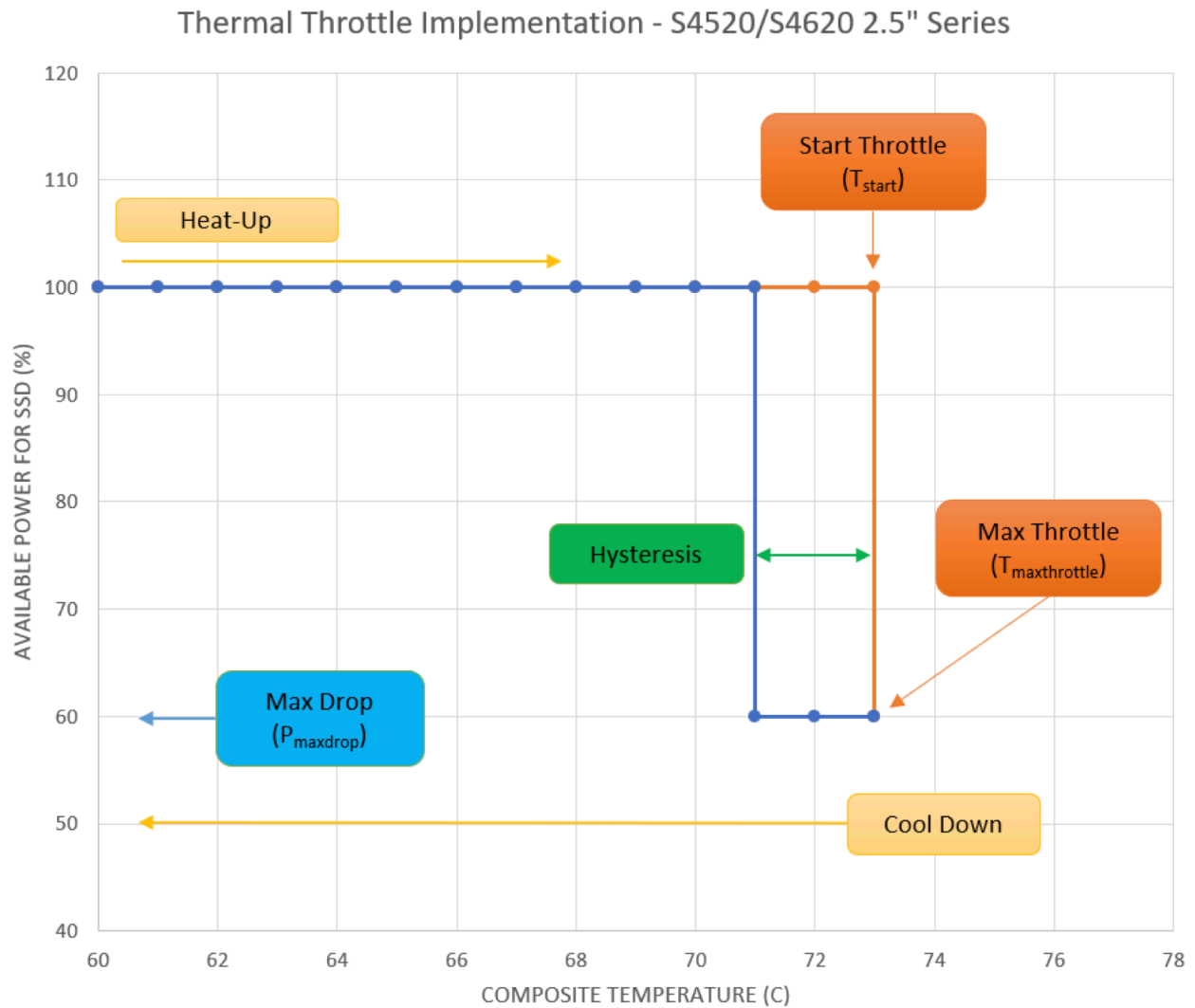
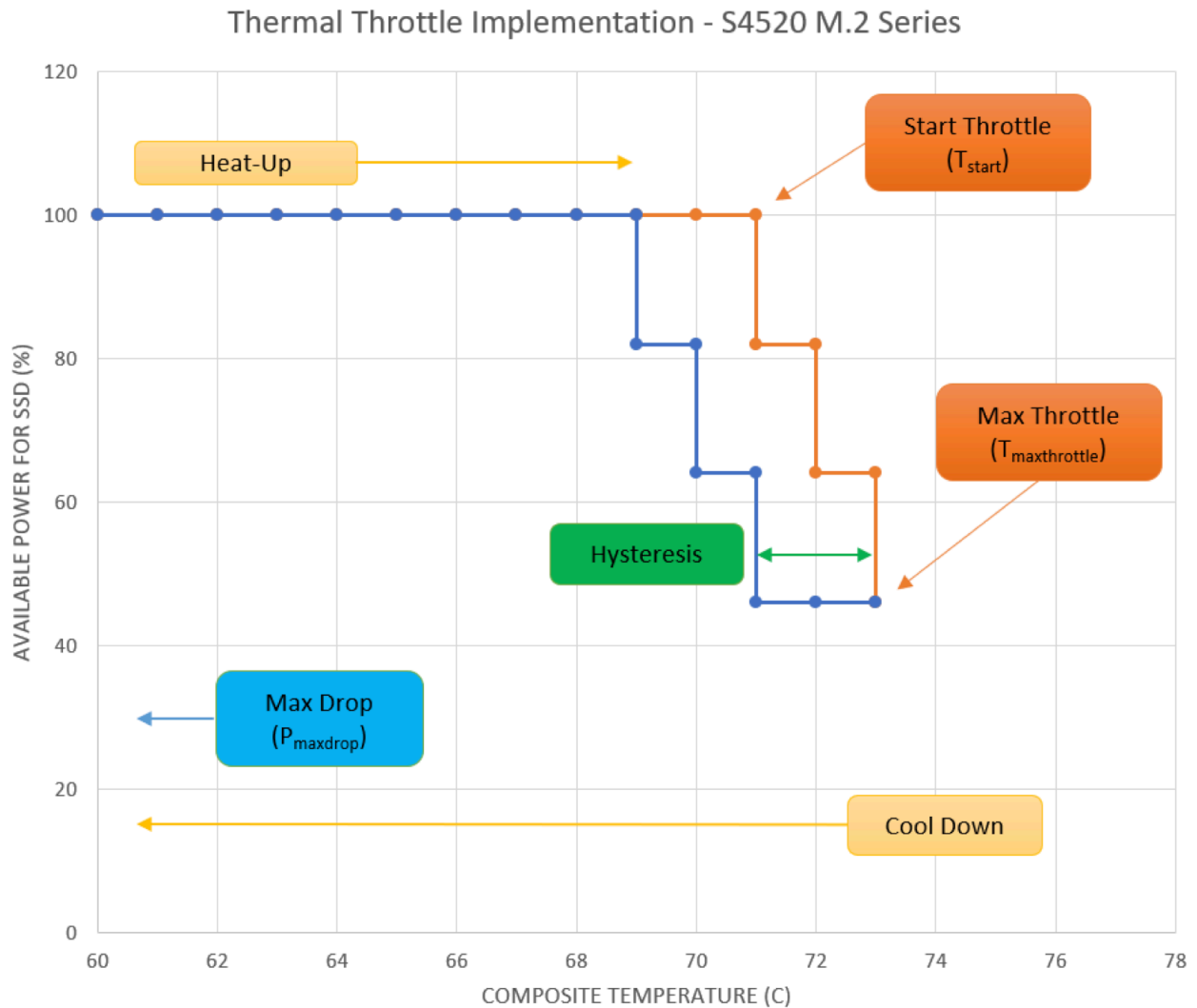


Figure 2.2: Thermal Throttling Behavior (M.2)



Shown above is the Thermal throttling behavior for Solidigm™ D3-S4520/D3-S4620 SKUs,  $P_{\text{maxdrop}}$  is 40% (2.5 inch), 50% (M.2),  $T_{\text{start}}$  is 73° C (2.5 inch), 71° C (M.2),  $T_{\text{maxthrottle}}$  is 73° C and N is 1 (2.5 inch), 3 (M.2).

The following table shows the Thermal throttle settings for Solidigm™ D3-S4520/D3-S4620 across all SKUs.

Table 22: Solidigm™ D3-S4520/D3-S4620 Thermal Throttle Settings

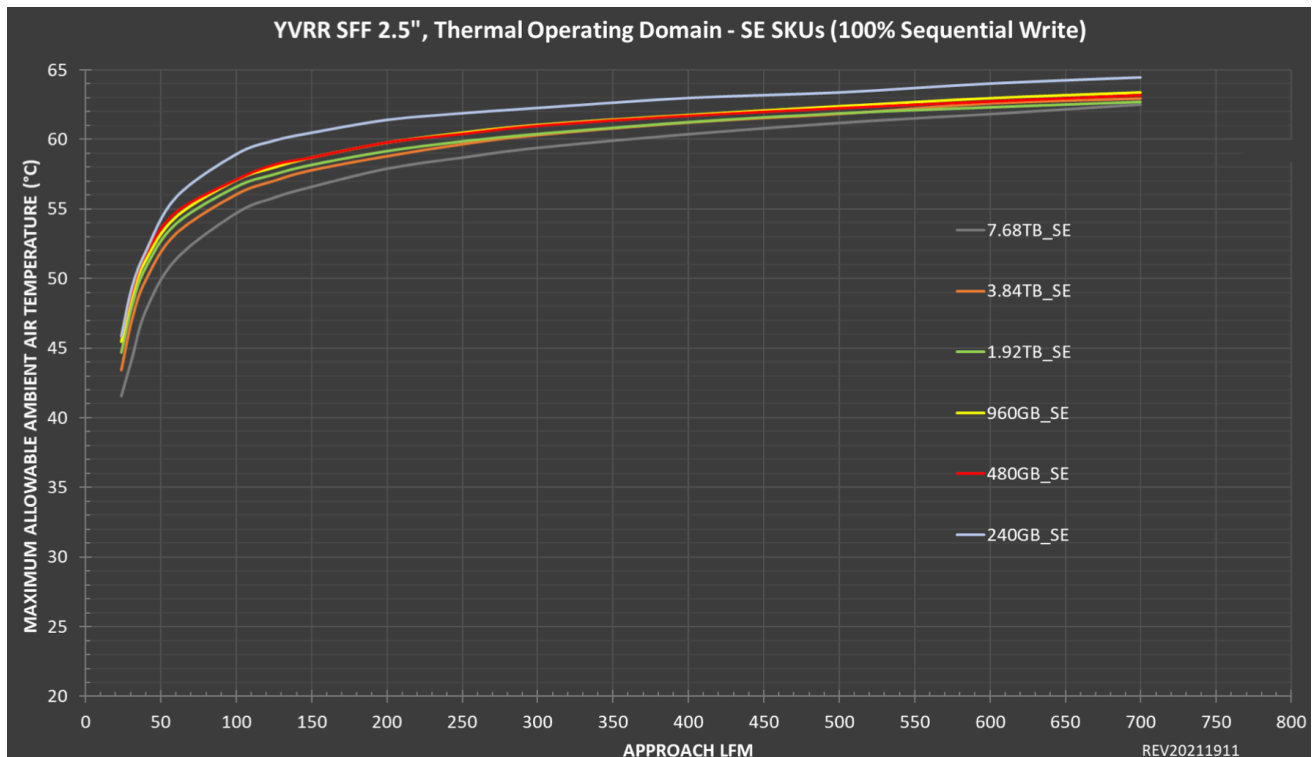
Product	Throttle Start	Throttle Max	Throttle Steps
D3-S4520/D3-S4620 (2.5 inch)	73° C	73° C	1
D3-S4520 (M.2)	71° C	73° C	3

## 2.5.1 Boundary Condition

To maintain SMART temperature BEh within thermal thresholds, the following air flow conditions are provided as an estimate.

Figure 3 shows the operating domain curve measured for Solidigm™ D3-S4520 240 GB, 480 GB, 960 GB, 1.92 TB, 3.84 TB, and 7.68 TB drives. Figure 4 shows the operating domain curve measured for Solidigm™ D3-S4620 480 GB, 960 GB, 1.92 TB, and 3.84 TB drives. The curves show allowable air inlet temperature vs. Flow Velocity (LFM) to prevent drive from exceeding thermal thresholds. Workload used to characterize the operating domain curve is 128KB Sequential Writes, Queue Depth 32 after the drive reaches steady state.

Figure 2.3: Solidigm™ D3-S4520 Operating Domain Curves (2.5 inch)



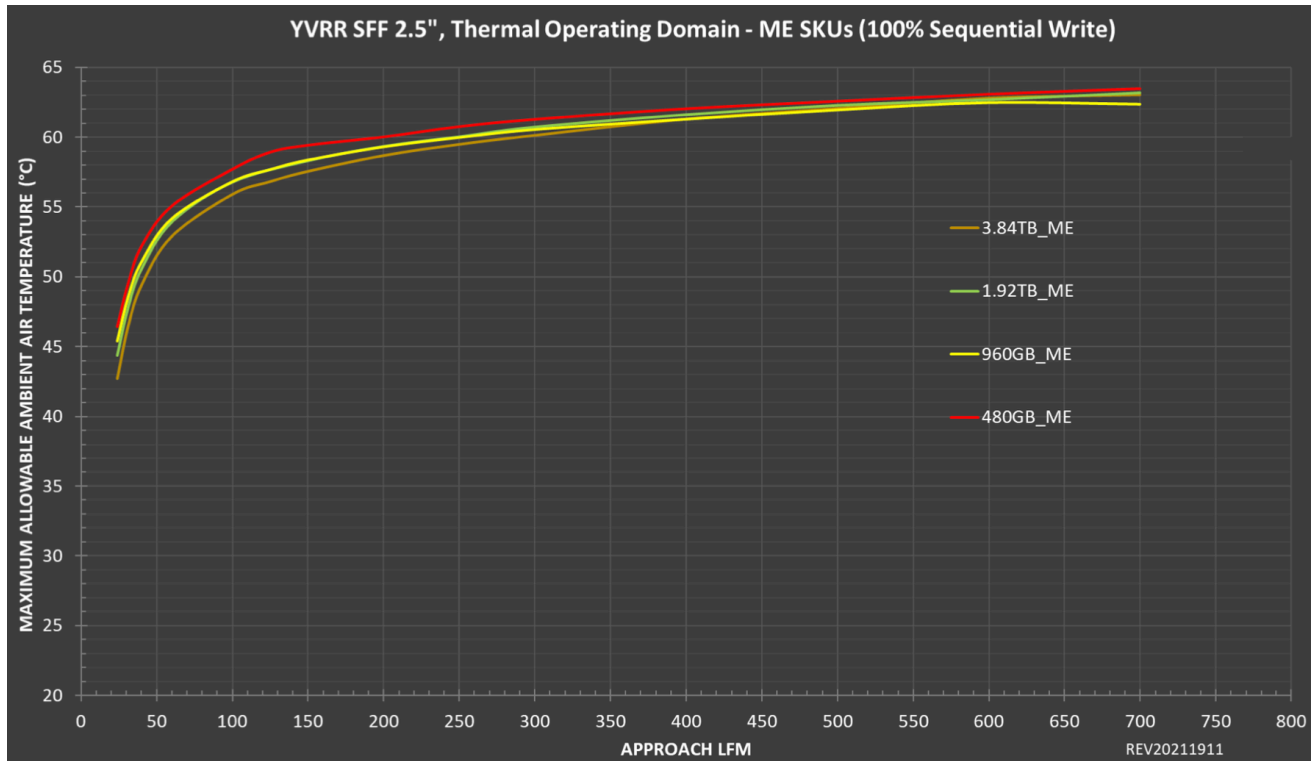
**Note:** Contact your Solidigm representative for details on operating domain curves.

Figure 2.4: Solidigm™ D3-S4520 Operating Domain Curves (M.2)



**Note:** Contact your Solidigm representative for details on operating domain curves.

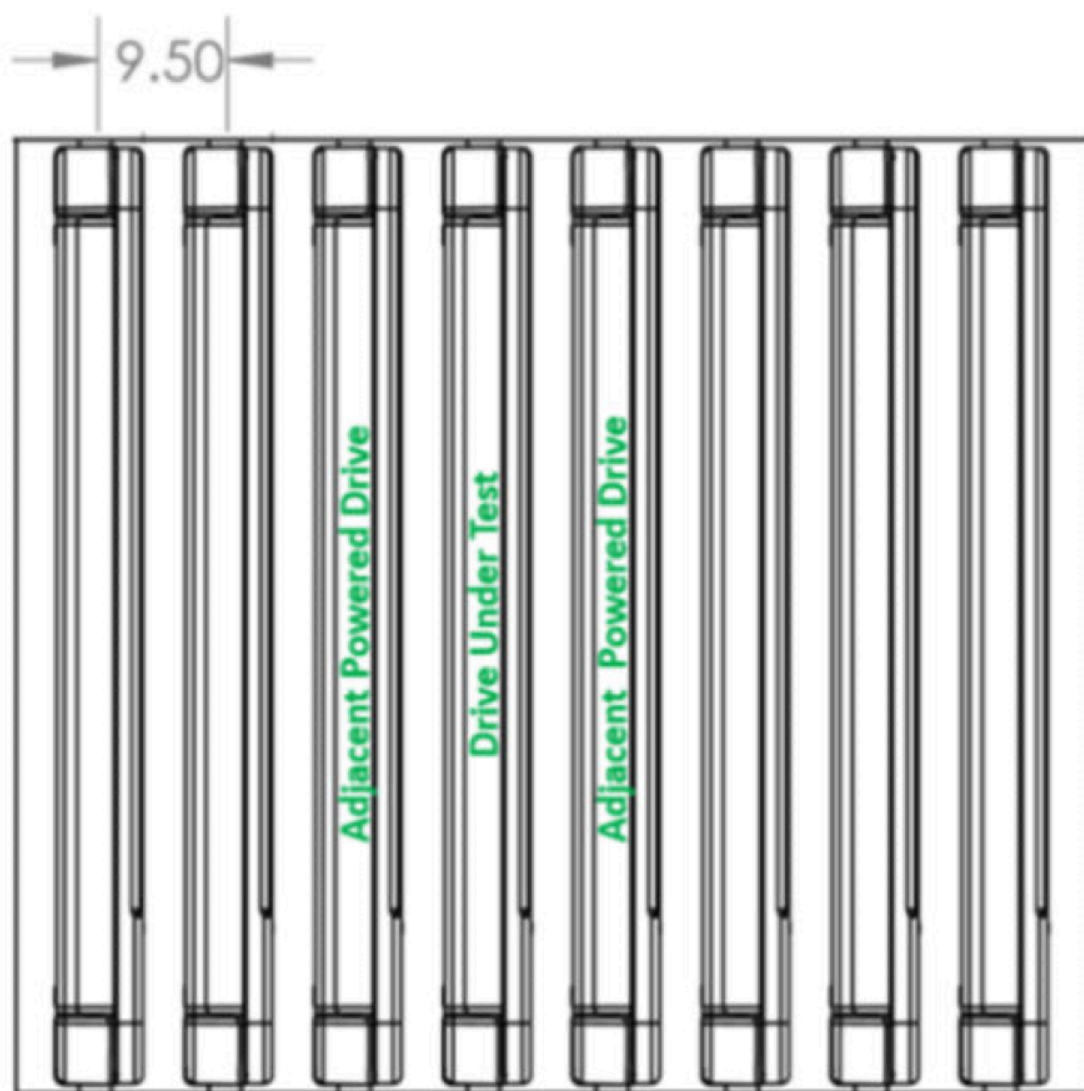
Figure 2.5: Solidigm™ D3-S4620 Operating Domain Curves (2.5 inch)



**Note:** Contact your Solidigm representative for details on operating domain curves.

Figure 2.5 shows the Drive Under Test with two Adjacent Powered Drives at 9.5-mm pitch, or 3-mm space between drives. Both Adjacent Drives act as heaters and are identical SKUs powered with the same 100% Sequential Write, 128KB and QD32 Workload as the Drive Under Test.

Figure 2.6: Drive Test Setup for Wind Tunnel Characterization



## 2.6 Product Regulatory Compliance

Solidigm™ D3-S4520/D3-S4620 drive meet or exceeds the regulatory or certification requirements in the following table. The following table applies to the production unit only.

**Table 23: Product Regulatory Compliance Specifications**

Title	Description	Region for Which Conformity Declared
TITLE 47 - Telecommunications CHAPTER 1 -- FEDERAL COMMUNICATIONS COMMISSION PART 15 -- RADIO FREQUENCY DEVICES ICES-003, Issue 4 Interference-Causing Equipment Standard Digital Apparatus	FCC Part 15B Class B CA/CSA-CEI/IEC CISPR 22:02. This is CISPR 22:1997 with Canadian Modifications	USA Canada
IEC 55035 Electromagnetic compatibility of multimedia equipment -- Immunity Requirements	EN-55035:2017 and its amendments	European Union
IEC 55022 Information Technology Equipment -- Radio disturbance Characteristics -- Limits and methods of measurement CISPR24:2008 (Modified)	EN-55022:2006 and its amendments	European Union
IEC 55032 Electromagnetic compatibility of multimedia equipment - Emission Requirements	EN-55032:2012 and its amendments	European Union
IEC/EN-60950-1 2 <sup>nd</sup> Edition <sup>1</sup>	Information Technology Equipment -- Safety -- Part 1: General Requirements	European Union
UL/CSA EN-60950-1 2 <sup>nd</sup> Edition	Information Technology Equipment -- Safety -- Part 1: General Requirements	USA/Canada
IEC/EN 62368-1 2 <sup>nd</sup> Edition	Audio/video, information and communication technology equipment -- Part 1: Safety requirements	European Union
UL/CSA 62368-1 2 <sup>nd</sup> Edition	Audio/video, information and communication technology equipment -- Part 1: Safety requirements	USA/Canada

**Note:**

- When airflow and ambient conditions described in section 2.5.1 are not met the SSD surface may exceed 70° C touch temperature and EN 62368-1 up to 80° C touch temperature applies. Refer to **Caution: Hot Surface** image in Certifications and Declarations [on page 49](#).

## 2.7 Reliability Specifications

Solidigm™ D3-S4520/D3-S4620 meets or exceeds SSD endurance and data retention requirements as specified in the JESD218 standard. Reliability specifications are listed in the table below.

**Table 24: Reliability Specifications**

Parameter	Value
Uncorrectable Bit Error Rate (UBER) <ul style="list-style-type: none"> <li>Uncorrectable bit error rate will not exceed one sector in the specified number of bits read. In the unlikely event of a non-recoverable read error, the SSD will report it as a read failure to the host; the sector in error is considered corrupt and is not returned to the host.</li> </ul>	< 1 sector per 10 <sup>17</sup> bits read
Mean Time Between Failures (MTBF) <ul style="list-style-type: none"> <li>Mean Time Between Failures is estimated based on Telcordia* methodology and demonstrated through Reliability Demonstration Test (RDT).</li> </ul>	2 million hours
Power On/Off Cycles <ul style="list-style-type: none"> <li>Power On/Off Cycles is defined as power being removed from the SSD, and then restored. Most host systems remove power from the SSD when entering suspend and hibernate as well as on a system shutdown.</li> </ul>	24 per day
Insertion Cycles (2.5-inch form factor only) <ul style="list-style-type: none"> <li>SATA/power cable insertion/removal cycles.</li> </ul>	50 on SATA cable 500 on backplane
Data Retention <ul style="list-style-type: none"> <li>The time period for retaining data in the NAND at maximum rated endurance.</li> </ul>	3 months power-off retention once SSD reaches rated write endurance at 40° C

**Table 25: Endurance Rating - D3-S4520**

Form Factor	Capacity	JEDEC Workload			128K Sequential Write		
		Endurance <sup>1</sup> (Petabyte Written)	DWPD (for 3 yrs.)	DWPD (for 5 yrs.)	Endurance <sup>1</sup> (Petabyte Written)	DWPD (for 3 yrs.)	DWPD (for 5 yrs.)
2.5" 7mm	240GB	1.0	4.1	2.5	2.5	9.8	5.9
	480GB	2.5	4.7	2.8	5.8	11.1	6.7
	960GB	5.3	5.1	3.0	12.4	11.8	7.0
	1.92TB	8.8	4.1	2.5	23.6	11.2	6.7
	3.84TB	15.3	3.6	2.1	43.4	10.3	6.1
	7.68TB	36.5	4.3	2.6	85.8	10.1	6.1
M.2	240GB	1.0	4.0	2.4	2.5	9.8	5.9
	480GB	4.1	7.8	4.7	7.0	13.3	7.9



**Note:**

1. Petabytes Written (PBW). Refer to JESD218 standard table 1 for UBER, FFR and other Enterprise SSD requirements. The number of drive writes such that the SSD meets the requirements according to the JESD218 standard. Endurance rating verification is defined to establish UBER <1E-16 at 60% upper confidence limit.

**Table 26: Endurance Rating – D3-S4620**

Form Factor	Capacity	JEDEC Workload			128K Sequential Write		
		Endurance <sup>1</sup> (Petabyte Written)	DWPD (for 3 yrs.)	DWPD (for 5 yrs.)	Endurance <sup>1</sup> (Petabyte Written)	DWPD (for 3 yrs.)	DWPD (for 5 yrs.)
2.5" 7mm	480GB	4.2	7.9	4.7	7.0	13.3	7.9
	960GB	7.1	6.7	4.0	13.5	12.8	7.7
	1.92TB	14.0	6.6	4.0	26.8	12.7	7.6
	3.84TB	35.1	8.3	5.0	55.3	13.1	7.8

**Note:**

1. Petabytes Written (PBW). Refer to JESD218 standard table 1 for UBER, FFR and other Enterprise SSD requirements. The number of drive writes such that the SSD meets the requirements according to the JESD218 standard. Endurance rating verification is defined to establish UBER <1E-16 at 60% upper confidence limit.

## 2.8 Temperature Sensor

The Solidigm™ D3-S4520/D3-S4620 has multiple temperature sensors with an accuracy of +/-2 °C over a range of -20°C to +100°C. However a **Composite Temperature** will be reported as the Drive Temperature. **Composite Temperature** is an artificial measurement that represents the minimum delta of any temperature monitored component to its unique warning limit, normalized to be a delta from 70° C.

$$\text{Temp}_{\text{Composite}} = 70 - \min(\text{Limit}_A - \text{CurTemp}_A, \text{Limit}_B - \text{CurTemp}_B, \text{Limit}_C - \text{CurTemp}_C, \dots, \text{Limit}_N - \text{CurTemp}_N)$$

Drive Composite Temperature can be monitored using SMART attribute: Drive Temperature (BEh). The thermal throttling of the drive is done based off composite temperature value. Worst case component temperature drives thermal throttling of the drive.

## 2.9 Power Loss Capacitor Test

The Solidigm™ D3-S4520/D3-S4620 supports testing of the power loss capacitor, which can be monitored using the following SMART attribute: (175, AFh).

## 2.10 Hot Plug Support

The D3-S4520/D3-S4620 2.5" form factor products support Hot Plug insertion and removal. The M.2 form factor does not natively support Hot Plug insertion and removal.

Hot Plug insertion and removal is supported in the presence of a proper connector and appropriate operating system (OS), as described in the SATA 3.1 specification.

The 2.5 inch form factor product supports asynchronous signal recovery and issues and unsolicited COMINIT when first mated with a powered connector to guarantee reliable detection by a host system without hardware device detection.

Hot Plug is not supported in the M.2 specification. However, the M.2 Solidigm™ Data Center SATA drives can support hot plug operations when used with an interposer design that electrically supports hot plug operations.

User Data is protected from planned or unplanned power loss by the Enhanced Power Management technology on all Solidigm™ Data Center drives.

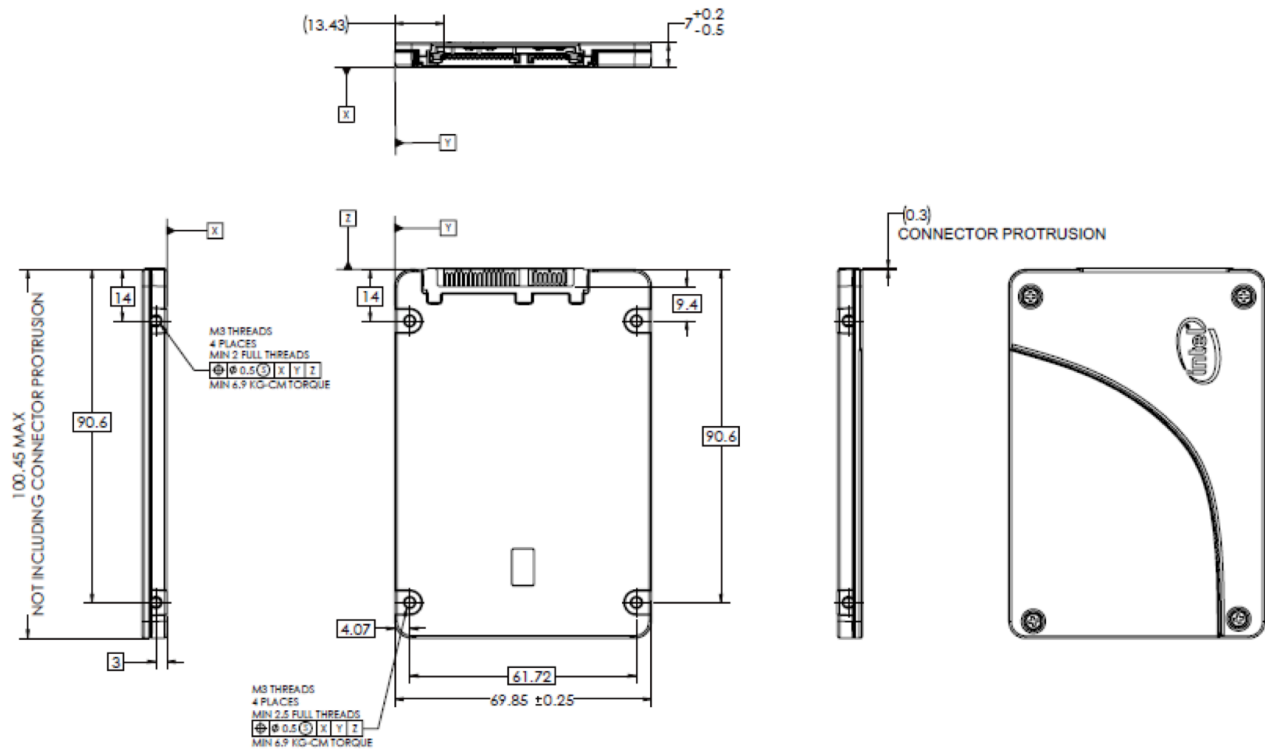
## 2.11 Hardware Based AES-XTS 256-bit Encryption Activated with ATA Password

The Solidigm™ D3-S4520/D3-S4620 supports hardware based full drive encryption and protects all user data at rest with AES-256 bit encryption. Access to user data on the drive can be authenticated at power-on using BIOS or ATA Security Feature Set.

### 3 Mechanical Information

The following figures show the physical package information for the Solidigm™ D3-S4520/D3-S4620 in the 2.5 inch and M.2 form factors. All dimensions are in millimeters.

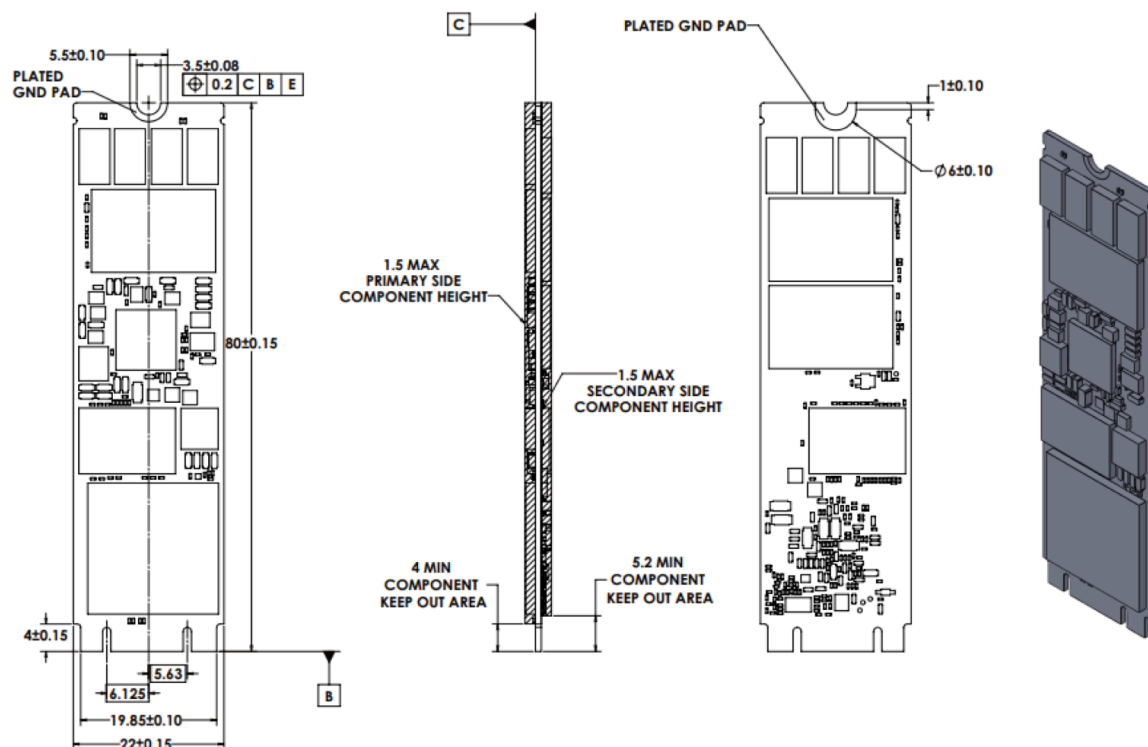
Figure 3.1: Solidigm™ D3-S4520/D3-S4620 2.5 inch 7mm Dimensions



X - Length	Y - Width	Z - Height
100.45 Max	69.85 +/- 0.25	7.0 +0.2/-0.5

**Note:** Length does not include 0.3 connector protrusion.

Figure 3.2: Solidigm™ D3-S4520 M.2 Dimensions



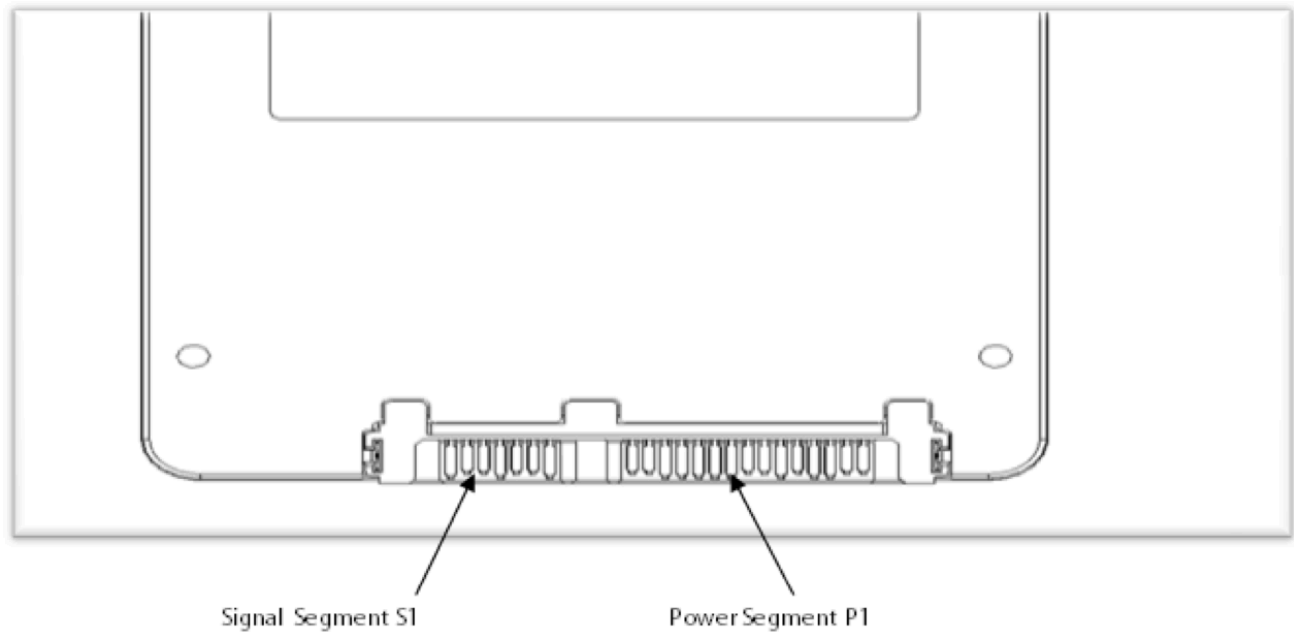
X - Length	Y - Width	Z - Height
80 +/- 0.15	22 +/- 0.15	3.6 +/- 0.28

## 4 Pin and Signal Descriptions

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### 4.1 2.5-inch Form Factor Pin Locations

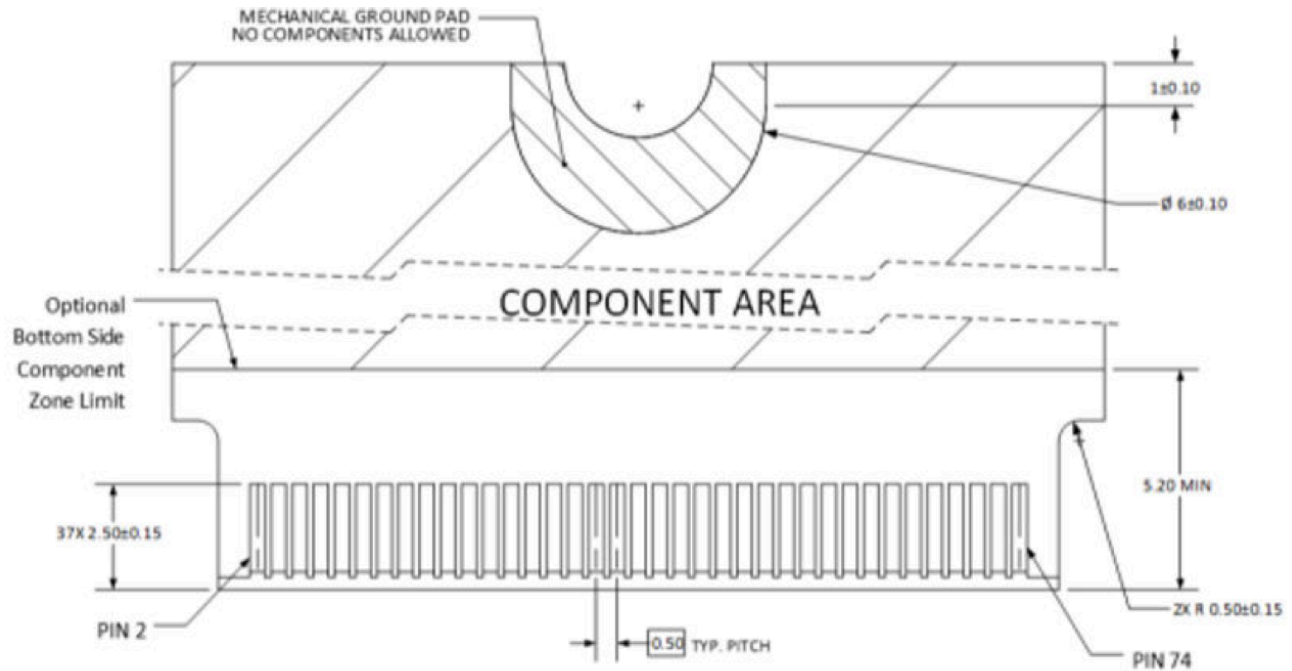
Figure 4.1: Layout of 2.5-inch Form Factor Signal and Power Segment Pins



**Note:** 2.5-inch connector supports built in latching capability.

### 4.2 M.2 Form Factor Pin Locations

Figure 4.2: Layout of M.2 Form Factor Signal and Power Segment Pins



### 4.3 Connector Pin Signal Definitions

Table 27: Serial ATA Connector Pin Signal Definitions - 2.5-inch Form Factors

Pin	Function	Definition
S1	Ground	1 <sup>st</sup> mate
S2	A+	Differential signal gain pair A
S3	A-	
S4	Ground	1 <sup>st</sup> mate
S5	B-	Differential signal gain pair B
S6	B+	
S7	Ground	1 <sup>st</sup> mate

**Note:** Key and spacing separate signal and power segments

### 4.4 Power Pin Signal Definitions

**Table 28: Serial ATA Power Pin Definitions—2.5-inch Form Factors**

Pin <sup>1</sup>	Function	Definition	Mating Order
P1 <sup>2</sup>	Not connected	(3.3V Power)	–
P2 <sup>2</sup>	Not connected	(3.3V Power)	–
P3 <sup>2</sup>	Not connected	(3.3V Power; pre-charge)	2 <sup>nd</sup> Mate
P4 <sup>3,4</sup>	Ground	Ground	1 <sup>st</sup> Mate
P5 <sup>3</sup>	Ground	Ground	1 <sup>st</sup> Mate
P6 <sup>3</sup>	Ground	Ground	1 <sup>st</sup> Mate
P7 <sup>3,5</sup>	V5	5V Power	1 <sup>st</sup> Mate
P8 <sup>3,5</sup>	V5	5V Power	2 <sup>nd</sup> Mate
P9 <sup>3,5</sup>	V5	5V Power	2 <sup>nd</sup> Mate
P10 <sup>3</sup>	Ground	Ground	1 <sup>st</sup> Mate
P11 <sup>6</sup>	DAS/DSS	Device Activity Signal/Device Staggered Spin-up	2 <sup>nd</sup> Mate
P12 <sup>3,4</sup>	Ground	Ground	1 <sup>st</sup> Mate
P13 <sup>7</sup>	V12	12V Power	1 <sup>st</sup> Mate
P14 <sup>7</sup>	V12	12V Power	2 <sup>nd</sup> Mate
P15 <sup>7</sup>	V12	12V Power	2 <sup>nd</sup> Mate

**Note:**

1. All pins are in a single row, with a 1.27 mm (0.050-inch) pitch.
2. Pins P1, P2 and P3 are connected together, although they are not connected internally to the device. The host may put 3.3V on these pins.
3. The mating sequence is:
  - Ground pins P4-P6, P10, P12 and the 5V power pin P7
  - Signal pins and the rest of the 5V power pins P8-P9
4. Ground connectors P4 and P12 may contact before the other 1st mate pins in both the power and signal connectors to discharge ESD in a suitably configured backplane connector.
5. Power pins P7, P8, and P9 are internally connected to one another within the device.
6. The host may ground P11 if it is not used for Device Activity Signal (DAS).
7. Pins P13, P14 and P15 are internally connected to one another within the device. The host may put 12V on these pins.

**Table 29: Serial ATA Power Pin Definitions-M.2 Form Factor Drives**

Pin	Function	Function	Pin
74	3.3V	GND	75
72	3.3V	GND	73
70	3.3V	GND	71
68	N/C	GND	69
x	Module Key M	N/C	67
x	Module Key M	Module Key M	x
x	Module Key M	Module Key M	x
x	Module Key M	Module Key M	x
58	Reserved for MFG_CLOCK	Module Key M	x
56	Reserved for MFG_DATA	GND	57
54	N/C	N/C	55
52	N/C	N/C	53
50	N/C	GND	51
48	N/C	SATA-A+	49
46	N/C	SATA-A-	47
44	N/C	GND	45
42	N/C	SATA-B-	43
40	N/C	SATA-B+	41
38	N/C	GND	39
36	N/C	N/C	37
34	N/C	N/C	35
32	N/C	GND	33
30	N/C	N/C	31
28	N/C	N/C	29
26	N/C	GND	27
24	N/C	N/C	25
22	N/C	N/C	23
20	N/C	GND	21
x	Module Key B	Module Key B	x



**Table 29: Serial ATA Power Pin Definitions-M.2 Form Factor Drives**

Pin	Function	Function	Pin
x	Module Key B	Module Key B	x
x	Module Key B	Module Key B	x
x	Module Key B	Module Key B	x
10	DAS/DSS#(I/O)	N/C	11
8	N/C	N/C	9
6	N/C	N/C	7
4	3.3V	N/C	5
2	3.3V	GND	3
		GND	1

## 5 Supported Command Sets

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The Solidigm™ D3-S4520/D3-S4620 supports all mandatory ATA (Advanced Technology Attachment) commands defined in the ATA8-ACS3 REV5F specification described in this section.

### 5.1 ATA General Feature Command Set

The Solidigm™ D3-S4520/D3-S4620 supports the ATA General Feature command set (non- PACKET), which consists of:

- EXECUTE DEVICE DIAGNOSTIC
- SET FEATURES
- IDENTIFY DEVICE

**Note:** See Appendix A, “IDENTIFY DEVICE Command Data” for details on the sector data returned after issuing an IDENTIFY DEVICE command.

The Solidigm™ D3-S4520/D3-S4620 also supports the following optional commands:

- READ DMA
- WRITE DMA
- READ SECTOR(S)
- READ VERIFY SECTOR(S)
- READ MULTIPLE
- SEEK
- SET FEATURES
- WRITE SECTOR(S)
- SET MULTIPLE MODE <sup>1</sup>
- WRITE MULTIPLE
- FLUSH CACHE
- READ BUFFER
- WRITE BUFFER
- NOP
- DOWNLOAD MICROCODE
- WRITE UNCORRECTABLE EXT

**Note:**

1. The only multiple supported will be multiple 1

### 5.2 Power Management Command Set

The Solidigm™ D3-S4520/D3-S4620 supports the Power Management command set, which consists of:

- CHECK POWER MODE
- IDLE
- IDLE IMMEDIATE
- SLEEP
- STANDBY
- STANDBY IMMEDIATE

## 5.3 Sanitize Feature Set

The Solidigm™ D3-S4520/D3-S4620 supports the Sanitize command set, which consists of:

- BLOCK ERASE EXT
- CRYPTO SCRAMBLE EXT
- OVERWRITE EXT
- SANITIZE ANTIFREEZE LOCK EXT
- SANITIZE FREEZE LOCK EXT
- SANITIZE STATUS EXT

## 5.4 Security Mode Feature Set

The Solidigm™ D3-S4520/D3-S4620 supports the Security Mode command set, which consists of:

- SECURITY SET PASSWORD
- SECURITY UNLOCK
- SECURITY ERASE PREPARE
- SECURITY ERASE UNIT
- SECURITY FREEZE LOCK
- SECURITY DISABLE PASSWORD

## 5.5 SMART Command Set

The Solidigm™ D3-S4520/D3-S4620 supports the SMART command set, which consists of:

- SMART READ DATA
- SMART READ ATTRIBUTE THRESHOLDS
- SMART ENABLE/DISABLE ATTRIBUTE AUTOSAVE
- SMART SAVE ATTRIBUTE VALUES
- SMART EXECUTE OFF-LINE IMMEDIATE
- SMART READ LOG SECTOR
- SMART WRITE LOG SECTOR
- SMART ENABLE OPERATIONS
- SMART DISABLE OPERATIONS
- SMART RETURN STATUS
- SMART ENABLE/DISABLE AUTOMATIC OFFLINE

### 5.5.1 Attributes

The following table lists the SMART attributes supported by the Solidigm™ D3-S4520/D3-S4620 and the corresponding status flags and threshold settings.

Table 30: SMART Attributes

ID	Attribute	Status Flags						Threshold
		SP	EC	ER	PE	OC	PW	
05h	Re-allocated Sector Count The raw value of this attribute shows the number of retired blocks since leaving the factory (grown defect count).	1	1	0	0	1	0	0 (none)
09h	Power-On Hours Count The raw value reports power-on time, cumulative over the life of the SSD, integer number in hour time units.	1	1	0	0	1	0	0 (none)
0Ch	Power Cycle Count The raw value of this attribute reports the cumulative number of power cycle events over the life of the device.	1	1	0	0	1	0	0 (none)
AAh	Available Reserved Space (See Attribute E8)	1	1	0	0	1	1	10
ABh	Program Fail Count The raw value of this attribute shows total count of program fails and the normalized value, beginning at 100, shows the percent remaining of allowable program fails.	1	1	0	0	1	0	0 (none)
ACh	Erase Fail Count The raw value of this attribute shows total count of erase fails and the normalized value, beginning at 100, shows the percent remaining of allowable erase fails.	1	1	0	0	1	0	0 (none)
AEh	Unexpected Power Loss Also known as “Power-off Retract Count” per magnetic-drive terminology. Reports number of unclean shutdowns, cumulative over the life of the SSD. An “unclean shutdown” is the removal of power without STANDBY IMMEDIATE as the last command (regardless of PLI activity using capacitor power).	1	1	0	0	1	0	0 (none)
AFh	Power Loss Protection Failure Last test result as microseconds to discharge cap, saturates at max value. Also logs minutes since last test and lifetime number of tests. Bytes 0-1: Last test result as microseconds to discharge cap, saturates at max value. Test result expected in range 25 <= result <= 5000000, lower indicates specific error code Bytes 2-3: Minutes since last test, saturates at max value. Bytes 4-5: Lifetime number of tests, not incremented on power cycle, saturates at max value.	1	1	0	0	1	1	10
B7h	SATA Downshift Count The count of the number of times SATA interface selected lower signaling rate due to error.	1	1	0	0	1	0	0 (none)

**Table 30: SMART Attributes**

ID	Attribute	Status Flags						Threshold
		SP	EC	ER	PE	OC	PW	
B8h	End-to-End Error Detection Count <i>Raw value:</i> reports number of LBA tag mismatches in end-to-end data protection path. <i>Normalized value:</i> always 100.	1	1	0	0	1	1	90
BBh	Uncorrectable Error Count <i>Raw value:</i> shows the count of errors that could not be recovered using Error Correction Code (ECC). <i>Normalized value:</i> always 100.	1	1	0	0	1	0	0 (none)
BEh	Drive Temperature Reports the SSD drivetemperature. <i>Raw value</i> suggests 100 - drivetemperature in C degrees.	1	0	0	0	1	0	0 (none)
C0h	Power-Off Retract Count (Unsafe Shutdown Count) The raw value of this attribute reports the cumulative number of unsafe (unclean) shutdown events over the life of the device. An unsafe shutdown occurs whenever the device is powered off without STANDBYIMMEDIATE being the last command.	1	1	0	0	1	0	0 (none)
C5h	Pending Sector Count Number of current unrecoverable read errors that will be re-allocated on next write.	0	1	0	0	1	0	0 (none)
C7h	CRC Error Count The total number of encountered SATA interface cyclic redundancy check (CRC) errors.	1	1	1	1	1	0	0 (none)
E1h	Host Writes The raw value of this attribute reports the total number of sectors written by the host system. The raw value is increased by 1 for every 65,536 sectors (32MB) written by the host.	1	1	0	0	1	0	0 (none)
E2h	Timed Workload Media Wear Measures the wear seen by the SSD (since reset of the workload timer, attribute E4h), as a percentage of the maximum rated cycles.	1	1	0	0	1	0	0 (none)
E3h	Timed Workload Host Read/Write Ratio Shows the percentage of I/O operations that are read operations (since reset of the workload timer, attribute E4h).	1	1	0	0	1	0	0 (none)
E4h	Timed Workload Timer Measures the elapsed time (number of minutes since starting this workload timer).	1	1	0	0	1	0	0 (none)

**Table 30: SMART Attributes**

ID	Attribute	Status Flags						Threshold
		SP	EC	ER	PE	OC	PW	
E8h	<p>Available Reserved Space</p> <p>This attribute reports the number of reserve blocks remaining. The normalized value begins at 100 (64h), which corresponds to 100 percent availability of the reserved space. The threshold value for this attribute is 10 percent availability.</p>	1	1	0	0	1	1	10
E9h	<p>Media Wearout Indicator</p> <p>This attribute reports the number of cycles the NAND media has undergone. The normalized value declines linearly from 100 to 1 as the average erase cycle count increases from 0 to the maximum rated cycles. Once the normalized value reaches 1, the number will not decrease, although it is likely that significant additional wear can be put on the device.</p>	1	1	0	0	1	0	0 (none)
EAh	<p>Thermal Throttle Status</p> <p>Reports Percent Throttle Status and Count of events</p> <p>Byte 0 = Throttling status. Decimal value 0 = No Throttle Applied, 100 = 100% throttling applied. Intermediate percentages are supported. A value larger than 100d is invalid.</p> <p>Bytes 1-4 = Throttling event count. 32 bit counter indicates the number of times thermal throttle has activated. Value is preserved over power cycles.</p> <p>Byte 5 = Reserved</p> <p>Normalized value: always 100.</p>	1	1	0	0	1	0	0 (none)
F1h	<p>Total LBAs Written</p> <p>The raw value of this attribute reports the total number of sectors written by the host system. The raw value is increased by 1 for every 65,536 sectors (32MB) written by the host.</p>	1	1	0	0	1	0	0 (none)
F2h	<p>Total LBAs Read</p> <p>The raw value of this attribute reports the total number of sectors read by the host system. The raw value is increased by 1 for every 65,536 sectors (32MB) read by the host.</p>	1	1	0	0	1	0	0 (none)
F3h	<p>Total Bytes Written</p> <p>The raw value of this attribute reports the total number of sectors written to the NAND media. This includes NAND writes triggered by host writes, defrag, background data refresh and wear level relocation writes etc. The raw value is increased by 1 for every 65,536 sectors (32MB) writes to the NAND media. Upon NAND write, new value returned once per minute.</p>	1	1	0	0	1	0	0 (none)

**Table 31: SMART Attribute Status Flags**

Status Flag	Description	Value = 0	Value = 1
SP	Self-preserving attribute	Not a self-preserving attribute	Self-preserving attribute
EC	Event count attribute	Not an event count attribute	Event count attribute
ER	Error rate attribute	Not an error rate attribute	Error rate attribute
PE	Performance attribute	Not a performance attribute	Performance attribute
OC	Online collection attribute	Collected only during offline activity	Collected during both offline and online activity
PW	Pre-fail warranty attribute	Advisory	Pre-fail

## 5.5.2 Timed Workload Endurance Indicators

### 5.5.2.1 Timed Workload Media Wear Indicator – ID E2h

This attribute tracks the drive wear seen by the device during the last wear timer loop, as a percentage of the maximum rated cycles. This value should be divided by 1024 to get the percentage.

For example: if the raw value is 4455, the percentage is  $4455/1024 = 4.35\%$ . The raw value is held at FFFFh until the wear timer (attribute E4h) reaches 60 (minutes) after a SMART EXECUTE OFFLINE IMMEDIATE (B0h/D4h) subcommand 40h to the SSD. The normalized value is always set to 100 and should be ignored.

### 5.5.2.2 Timed Workload Host Reads Percentage – ID E3h

This attribute shows the percentage of I/O operations that are read operations during the last workload timer loop. The raw value tracks this percentage and is held at FFFFh until the workload timer (attribute E4h) reaches 60 (minutes). The normalized value is always set to 100 and should be ignored.

### 5.5.2.3 Workload Timer – ID E4h

This attribute is used to measure the time elapsed during the current workload. The attribute is reset when a SMART EXECUTE OFFLINE IMMEDIATE (D4h) subcommand 40h is issued to the drive. The raw value tracks the time in minutes and has a maximum value of  $2^{32} = 4,294,967,296$  minutes (8,171 years). The normalized value is always set to 100 and should be ignored.

### 5.5.2.4 User Notes

- Sending a SMART EXECUTE OFFLINE IMMEDIATE (B0h/D4h) subcommand 40h to the SSD resets and starts all three attributes (Media Wear Indicator, Attribute E2h, Host Reads Percentage, Attribute E3h, and the Workload timer, Attribute E4h to FFFFh.
- The Attribute raw values are held at FFFFh until the Workload timer (Attribute E4h) reaches a total of 60 (minutes) of power on time. After 60 minutes, the Timed Workload data is made available.
- After the Workload timer (E4h) reaches 60 (minutes), the Timed Workload data is saved every minute so only 59 seconds of data

is lost if power is removed without receiving ATA STANDBY IMMEDIATE. Accumulated data is not reset due to power loss.

- Upon power up, the attributes hold a snapshot of their last saved values for 59 seconds and live data is available after 60 seconds, once the initial one hour interval is completed.

### 5.5.2.5 Example Use Cases

The Timed Workload Endurance attributes described in this section are intended to be used to measure the amount of media wear that the drive is subjected to during a timed workload.

Ideally, the system that the drive is being used in should be capable of issuing SMART commands. Otherwise, provisions have been provided to allow the media wear attributes to be persistent so the drive can be moved to a SMART capable system to read out the drive wear attribute values.

### 5.5.2.6 Use Case 1 - With a System Capable of SMART Commands

1. On a SMART capable system, issue the SMART EXECUTE OFF-LINE IMMEDIATE (D4h) sub-command 40h to reset the drive wear attributes.
2. Run the workload to be evaluated for at least 60 minutes. Otherwise the drive wear attributes will not be available.
3. Read out the drive wear attributes with the SMART READ DATA (D0h) command.

### 5.5.2.7 Use Case 2 - With a System Not Capable of SMART Commands

1. On a SMART capable system, issue the SMART EXECUTE OFF-LINE IMMEDIATE (D4h) sub-command 40h to reset the drive wear attributes.
2. Move the drive to the system where the workload will be measured (and not capable of SMART commands).
3. Run the workload to be evaluated for at least 60 minutes. Otherwise the drive wear attributes will not be available.
4. Do a clean system power down by issuing the ATA STANDBY IMMEDIATE command prior to shutting down the system. This will store all the drive wear SMART attributes to persistent memory within the drive.
5. Move the drive to a SMART capable system.
6. Read out the drive wear attributes with the SMART READ DATA (D0h) command within 59 seconds after power-up.

### 5.5.2.8 Example Calculation of Drive Wear

The following is an example of how the drive wear attributes can be used to evaluate the impact of a given workload. The Host Writes SMART attribute (E1h) can also be used to calculate the amount of data written by the host during the workload by reading this attribute before and after running the workload. This example assumes that the steps shown in Example Use Cases [on page 44](#) were followed to obtain the following attribute values:

- Timed Workload Media Wear (E2h) has a raw value of 16. Therefore, the percentage wear =  $16/1024 = 0.016\%$ .
- Timed Workload Host Read/Write Ratio (E3h) has a normalized value of 80, indicating that 80% of operations were reads.
- Workload Timer (E4h) has a raw value of 500. Therefore the workload ran for 500 minutes.
- Host Writes Count (E1h) had a raw value of 100,000 prior to running the workload and a value of 130,000 at the end of the workload. Therefore, the number of sectors written by the host during the workload was  $30,000 * 65,535 = 1,966,050,000$  sectors or  $1,966,050,000 * 512/1,000,000,000 = 1,007$  GB.

The following conclusions can be made for this example case:



The workload took 500 minutes to complete with 80% reads and 20% writes. A total of 1,007 GB of data was written to the device, which increased the media wear in the drive by 0.016%. At this point in time, this workload is causing a wear rate of 0.016% for every 500 minutes, or 0.00192%/hour.

### 5.5.3 SMART Logs

The Solidigm™ D3-S4520/D3-S4620 implements the following Log Addresses: 00h, 02h, 03h, 06h, and 07h.

The D3-S4520/D3-S4620 implements host vendor specific logs (addresses 80h-9Fh) as read and write scratchpads, where the default value is zero (0). Solidigm™ D3-S4520/D3-S4620 does not write any specific values to these logs unless directed by the host through the appropriate commands.

The D3-S4520/D3-S4620 also implements a device vendor specific log at address A9h as a read-only log area with a default value of zero (0). Besides that, the D3-S4520/D3-S4620 also implements log address B8h (if the drive is in disable logical mode, log address B8h will have a failure code). Finally, the D3-S4520/D3-S4620 also implements log at addresses B9h and BAh (both of them are Solidigm error logs, and read only for customers).

## 5.6 Device Statistics

In addition to the SMART attribute structure, statistics pertaining to the operation and health of the Solidigm™ D3-S4520/D3-S4620 can be reported to the host on request through the Device Statistics log as defined in the ATA specification.

The Device Statistics log is a read-only GPL/SMART log located at read log address 0x04 and is accessible using READ LOG EXT, READ LOG DMA EXT or SMART READ LOG commands.

The following table lists the Device Statistics supported by the Solidigm™ D3-S4520/D3-S4620.

**Table 32: Device Statistics**

Page	Offset	Description	Equivalent SMART attribute (if applicable)
0x00	--	List of Supported Pages	–
0x01 – General Statistics	0x08	Power Cycle Count	0Ch
	0x10	Power-On Hours	09h
	0x18	Logical Sectors Written	E1h
	0x20	Num Write Commands - incremented by one for every host write	–
	0x28	Logical Sectors Read	F2h
	0x30	Num Read Commands - incremented by one for every host read	–

**Table 32: Device Statistics**

Page	Offset	Description	Equivalent SMART attribute (if applicable)
0x04 – General Error Statistics	0x08	Num Reported Uncorrectable Errors	BBh
	0x10	Num Resets Between Command Acceptance and Completion	–
0x05 – Temperature Statistics	0x00	Device Statistics Information Header	–
	0x08	Current Temperature	–
	0x10	Average Short Term Temperature	–
	0x18	Average Long Term Temperature	–
	0x20	Highest Temperature	–
	0x28	Lowest Temperature	–
	0x30	Highest Average Short Term Temperature	–
	0x38	Lowest Average Short Term Temperature	–
	0x40	Highest Average Long Term Temperature	–
	0x48	Lowest Average Long Term Temperature	–
	0x50	Time in Over-Temperature	–
	0x58	Specified Maximum Operating Temperature	–
	0x60	Time in Under-Temperature	–
	0x68	Specified Minimum Operating Temperature	–
	0x70	Number of times drive entered Thermal Throttle	–
0x06 – Transport Statistics	0x08	Number of Hardware Resets	–
	0x10	Number of ASR Events	–
	0x18	Number of Interface CRC Errors	–
0x07 – Solid State Device Statistics	0x08	Percentage Used Endurance Indicator	E9h <sup>1</sup>

**Note:**

1. This device statistic counts from 1 to 150

## 5.7 SMART Command Transport (SCT)

With SMART Command Transport (SCT), a host can send commands and data to an SSD and receive status and data from an SSD using standard write/read commands to manipulate two SMART Logs:

- Log Address E0h ("SCT Command/Status") – used to send commands and retrieve status
- Log Address E1h ("SCT Data Transfer") – used to transport data

Solidigm™ D3-S4520/D3-S4620 supports the following standard SCT actions:

- Write Same – D3-S4520/D3-S4620 implements this action code as described in the ATA specification.
- Error Recovery Control – D3-S4520/D3-S4620 accepts this action code and will store and return error-recovery time limit values.
- Feature Control - D3-S4520/D3-S4620 supports feature code 0001h (write cache) feature code 0002h (write cache reordering), and feature code 0003h (time interval for temperature logging). It also supports D000h (Power Safe Write Cache capacitor test interval), D001h (read/write power governor mode), D002h (read thermal governor mode), D003h (read power governor burst power), and D004h (read power governor average power).
- Data table command - D3-S4520/D3-S4620 supports data table command as specified in ATA8-ACS3 REV5. This will read out temperature logging information in table ID 0002h.
- Read Status Support - D3-S4520/D3-S4620 supports read status log
- By using SCT command 0xD801 with State=0, Option=1, ID Word 106 can be changed from 0x6003 to 0x4000 (4KB physical sector size to 512B physical sector size support change).

## 5.8 Data Set Management Command Set

Solidigm™ D3-S4520/D3-S4620 supports the Data Set Management command set Trim attribute, which consists of:

- DATA SET MANAGEMENT

## 5.9 Accessible Max Address Configuration Command Set

Solidigm™ D3-S4520/D3-S4620 supports the Accessible Max Address Configuration Command set, which consists of:

- GET NATIVE MAX ADDRESS EXT
- SET ACCESSIBLE MAX ADDRESS EXT
- FREEZE ACCESSIBLE MAX ADDRESS EXT

## 5.10 48-Bit Address Command Set

Solidigm™ D3-S4520/D3-S4620 supports the 48-bit Address command set, which consists of:

- FLUSH CACHE EXT
- READ DMA EXT
- READ NATIVE MAX ADDRESS EXT
- READ SECTOR(S) EXT
- READ VERIFY SECTOR(S) EXT

- SET MAX ADDRESS EXT
- WRITE DMA EXT
- WRITE MULTIPLE EXT
- WRITE SECTOR(S) EXT
- WRITE MULTIPLE FUA EXT
- WRITE DMA FUA EXT

## 5.11 General Purpose Log Command Set

Solidigm™ D3-S4520/D3-S4620 supports the General Purpose Log command set, which consists of:

- READ LOG EXT
- WRITE LOG EXT

## 5.12 Native Command Queuing

Solidigm™ D3-S4520/D3-S4620 supports the Native Command Queuing (NCQ) command set, which includes:

- READ FPDMA QUEUED
- WRITE FPDMA QUEUED

**Note:** With a maximum Queue Depth set to 32.

## 5.13 Software Settings Preservation

Solidigm™ D3-S4520/D3-S4620 supports the SET FEATURES parameter to enable/disable the preservation of software settings.

## 6 Certifications and Declarations

The following table describes the Device Certifications supported by the Solidigm™ D3-S4520/D3-S4620.

**Table 33: Device Certifications and Declarations**


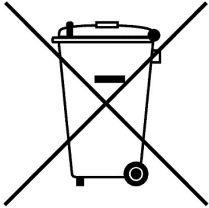












Certification	Description
CE Compliant 	<p>European Economic Area (EEA): Compliance with the essential requirements of EC Council Directives Low Voltage Directive (LVD) 2014/35/EU and EMC Directive 2014/30/EU.</p> <p>Compliance with Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment</p>
EU WEEE  	<p>Compliance with Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE)</p>
UL Recognized 	<p>Certified Underwriters Laboratories, Inc. Bi-National Component Recognition; UL 60950-1, 2nd Edition, 2014-10-14 [Information Technology Equipment - Safety - Part 1: General Requirements].</p> <p>CSA C22.2 No. 60950-1-07, 2nd Edition, 2014-010 (Information Technology Equipment - Safety - Part 1: General Requirements)</p> <p>These products have been Complimentary Recognized to UL/CSA 62368-1, 2nd Edition [Audio/video, information and communication technology equipment - Part 1: Safety requirements]</p>  <p><b>"CAUTION: Hot Surface, Do not touch the SSD surface"</b>  <b>"Attention: Surface Chaude. Ne touchez pas la surface"</b></p>
UKCA 	<p>Great Britain (England, Wales and Scotland): compliance with UK S.I. No.1101, Electrical Equipment (Safety) Regulations 2016, UK S.I. No. 1091, Electromagnetic Compatibility Regulations 2016, and UK S.I. No. 3032, The Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment Regulations 2012.</p>
Australia / New Zealand: RCM 	<p>Compliance with the Australia/New Zealand Standard(s) AS/NZ CISPR 32:2015 and AS/NZ CISPR 22:2009 +A1:2010, In compliance with the Radiocommunications Act 1992 as part of the ACMA's Electromagnetic Compatibility (EMC) Regulatory Arrangement and RSM Radiocommunications (EMC Standards) Notice 2015.</p>

Table 33: Device Certifications and Declarations

Certification	Description
Taiwan BSMI  <b>D3E906</b> <b>RoHS</b>	Compliance to the Taiwan EMC standard CNS 13438: Information technology equipment - Radio disturbance Characteristics - limits and methods of measurement, as amended on June 1, 2006, is harmonized with CISPR 22: 2005.04. Compliance to the Taiwan CNS 15663 [Guidance to reduction of the restricted chemical substances in electrical and electronic equipment (EEE)].
Korea KCC 	Compliance with paragraph 1 of Article 11 of the Electromagnetic Compatibility Control Regulation and meets the Electromagnetic Compatibility (EMC) Framework requirements of the Radio Research Laboratory (RRL) Ministry of Information and Communication Republic of Korea.
Morocco Maghreb 	Compliant with Decree # 2574-14 (EMC) on electromagnetic compatibility
Canada ICES <b>CAN ICES-3</b> <b>(B)/NMB-3(B)</b>	Compliance with Innovation, Science and Economic Development Canada standard ICES-003.
Japan VCCI 	Voluntary Control Council for Interface to cope with disturbance problems caused by personal computers or facsimile.
China EFUP 	China Environmentally Friendly Use Period (EFUP) symbol. Compliance with GB/T 26572: Requirements on concentration limits for certain restricted substances in electrical and electronic products.

**Table 33: Device Certifications and Declarations**

Certification	Description
Ukraine RoHS 	Compliant with TECHNICAL REGULATION on the restriction of the use of certain hazardous substances in electrical and electronic equipment APPROVED by Resolution of the Cabinet of Ministers of Ukraine of 10 March 2017 No. 139.
Low Halogen	Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Solidigm components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB/substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.
Microsoft WHCP 	The windows Hardware Compatibility Program is designed to help Microsoft partners to deliver compatible and reliable systems, software, and hardware products. End users trust the logo as an assurance of compatibility and reliability. This program is intended to help partners develop systems and devices that have been tested to ensure that they meet Microsoft standards for Windows as well as the quality level that ensures a great Windows experience for end users.

## 7 References

The following table identifies the standards information referenced in this document.

**Table 34: Standards References**

Date	Title	Location
October 2013	ACS-3-ATA/ATAPI Command Set 3 Specification	<a href="http://www.t13.org/">http://www.t13.org/</a>
July 2011	Serial ATA Revision 3.1	<a href="http://www.sata-io.org/">http://www.sata-io.org/</a>
July 2012	Solid State Drive (SSD) Endurance Workloads (JESD219)	<a href="http://www.jedec.org/standards-documents/results/jesd219">http://www.jedec.org/standards-documents/results/jesd219</a>
Sept 2010	Solid-State Drive (SSD) Requirements and Endurance Test Method (JESD218)	<a href="http://www.jedec.org/standards-documents/docs/jesd218/">http://www.jedec.org/standards-documents/docs/jesd218/</a>
June 2009	RoHS	<ul style="list-style-type: none"> <li>• <a href="https://www.solidigm.com/products/data-center/d3/s4520.html">https://www.solidigm.com/products/data-center/d3/s4520.html</a></li> <li>• <a href="https://www.solidigm.com/products/data-center/d3/s4620.html">https://www.solidigm.com/products/data-center/d3/s4620.html</a></li> </ul> Scroll down to <i>PCN &amp; MDDS</i> and click on <i>MDDS</i>
Dec 2008	VCCI	<a href="http://www.vcci.jp/vcci_e/">http://www.vcci.jp/vcci_e/</a>
May 2006	SFF-8223, 2.5-inch Drive w/Serial Attachment Connector	<a href="http://www.sffcommittee.org/">http://www.sffcommittee.org/</a>
May 2005	SFF-8201, 2.5-inch drive form factor	<a href="http://www.sffcommittee.org/">http://www.sffcommittee.org/</a>
1995	ENV 50204 (Radiated electromagnetic field from digital radio telephones)	
1995 1996 1995 1995 1997 1994	International Electrotechnical Commission EN 61000 4-2 (Electrostatic discharge immunity test) 4-3 (Radiated, radio-frequency, electromagnetic field immunity test) 4-4 (Electrical fast transient/burst immunity test) 4-5 (Surge immunity test) 4-6 (Immunity to conducted disturbances, induced by radio-frequency fields) 4-11 (Voltage Variations, voltage dips, short interruptions and voltage variations immunity tests)	<a href="http://www.iec.ch/">http://www.iec.ch/</a>



# Appendix

## Appendix A: IDENTIFY Device Command Data

Table 35: Returned Sector Data

Word	F = Fixed V = Variable X = Both	Default Value	Description
0	X	0040h	General configuration bit-significant information
1	X	3FFFh	Obsolete - Number of logical cylinders (16,383)
2	V	C837h	Specific configuration
3	X	0010h	Obsolete - Number of logical heads (16)
4-5	X	0h	Retired
6	X	003Fh	Obsolete - Number of logical sectors per logical track (63)
7-8	V	0h	Reserved for assignment by the CompactFlash Association (CFA)
9	X	0h	Retired
10-19	F	varies	Serial number (20 ASCII characters)
20-21	X	0h	Retired
22	X	0h	Obsolete
23-26	F	varies	Firmware revision (8 ASCII characters)
27-46	F	varies	Model number (Solidigm™ Solid-State Drive) <sup>1</sup>
47	F	8001h	7:0—Maximum number of sectors transferred per interrupt on multiple commands
48	F	4000h	Trusted Computing Feature Set
49	F	2F00h	Capabilities
50	F	4000h	Capabilities
51-52	X	0h	Obsolete
53	F	0006h	Words 88 and 70:64 valid
54-58	X	00FBFh	Obsolete
59	F	FD01h	Number of sectors transferred per interrupt on multiple commands

**Table 35: Returned Sector Data**

Word	F = Fixed V = Variable X = Both	Default Value	Description
60-61	V	240 GB: 0FFFFFFFh 480 GB: 0FFFFFFFh 960 GB: 0FFFFFFFh 1920 GB: 0FFFFFFFh 3840 GB: 0FFFFFFFh 7680 GB: 0FFFFFFFh	Total number of user-addressable sector for 28-bit commands
62	X	0h	Obsolete
63	X	0007h	Multi-word DMA modes supported/selected
64	F	0003h	PIO modes supported
65	F	0078h	Minimum multiword DMA transfer cycle time per word
66	F	0078h	Manufacturer's recommended multiword DMA transfer cycle time
67	F	0078h	Minimum PIO transfer cycle time without flow control
68	F	0078h	Minimum PIO transfer cycle time with IORDY flow control
69	F	403Ch	Additional Supported
70	F	0000h	Reserved
71-74	F	0h	Reserved for IDENTIFY PACKET DEVICE command
75	F	001Fh	Queue depth
76	F	850Eh	Serial ATA capabilities
77	F	0006h	Reserved for future Serial ATA definition
78	F	0040h	Serial ATA features supported
79	V	0040h	Serial ATA features enabled
80	F	07FCh	Major version number
81	F	006Dh	Minor version number
82	F	706Bh	Command set supported
83	F	7401h	Command sets supported
84	F	6163h	Command set/feature supported extension
85	X	7069h	Command set/feature enabled

**Table 35: Returned Sector Data**

Word	F = Fixed V = Variable X = Both	Default Value	Description
86	X	B401h	Command set/feature enabled
87	X	6163h	Command set/feature default
88	X	407Fh	Ultra DMA Modes
89	F	0001h	Time required for security erase unit completion
90	F	0001h	Time required for enhanced security erase completion
91	V	0h	Current advanced power management value
92	V	FFFEh	Master Password Revision Code
93	X	0h	Hardware reset result: the contents of bits (12:0) of this word shall change only during the execution of a hardware reset
94	V	0h	Vendor's recommended and actual acoustic management value
95	F	0h	Stream minimum request size
96	V	0h	Streaming transfer time - DMA
97	V	0h	Streaming access latency - DMA and PIO
98-99	F	0h	Streaming performance granularity
100-103	V	240 GB: 1BF244B0h 480 GB: 37E436B0h 960 GB: 6FC81AB0h 1920 GB: 8BBA0CB0h 3840 GB: BA4D4AB0h 7680 GB: 37E3E92B0	Maximum user LBA for 48-bit address feature set
104	V	0h	Streaming transfer time - PIO
105	V	0004h	Maximum number of 512-byte blocks of LBA Range Entries per DATA SET MANAGEMENT command
106	F	6003h	Physical sector size / logical sector size - User Changeable by SCT command to report 512B
107	F	0h	Inter-seek delay for ISO-7779 acoustic testing in microseconds
108-111	F	varies	Unique ID
112-115	F	0h	Reserved for worldwide name extension to 128 bits

**Table 35: Returned Sector Data**

Word	F = Fixed V = Variable X = Both	Default Value	Description
116	V	0h	Reserved for technical report
117-118	F	0h	Words per logical sector
119	F	415Ch	Supported settings
120	X	411Ch	Command set/feature enabled/supported
121-126	F	0h	Reserved
127	X	0h	Removable Media Status Notification feature set support
128	X	0029h	Security status
129-159	V	0h	Vendor-specific
160	X	0h	CompactFlash Association (CFA) power mode 1
161-167	X	0h	Reserved for assignment by the CFA
168	X	0003h	Device Nominal Form Factor
169	X	0001h	Data set management Trim attribute support
170-175	F	0h	Reserved for assignment by the CFA
176-205	V	Varies	Current media serial number
206	X	003Dh	SCT Command Transport
207-208	F	0000h	Reserved
209	X	4000h	Alignment of logical blocks within a physical block
210-211	V	0000h	Write-Read-Verify Sector Count Mode 3 (DWord)
212-213	F	0000h	Write-Read-Verify Sector Count Mode 2 (DWord)
214-216	X	0000h	Obsolete
217	F	0001h	Nominal media rotation rate
218	V	0000h	Reserved
219	F	0000h	Obsolete
220	V	0000h	Reserved
221	X	0000h	Reserved
222	F	10FFh	Transport major version number
223	F	0000h	Transport minor version number
224-233	F	0000h	Reserved

**Table 35: Returned Sector Data**

Word	F = Fixed V = Variable X = Both	Default Value	Description
234	F	0001h	Minimum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
235	F	FFFFh	Maximum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
236-254	X	0000h	Reserved
255	V	Varies	Integrity word

**Note:**

1. Intel® Series D3-S4520/D3-S4620 will report the Model number as Intel®.

**F = Fixed.** The content of the word is fixed and does not change. For removable media devices, these values may change when media is removed or changed.

**V = Variable.** The state of at least one bit in a word is variable and may change depending on the state of the device or the commands executed by the device.

**X = F or V.** The content of the word may be fixed or variable.